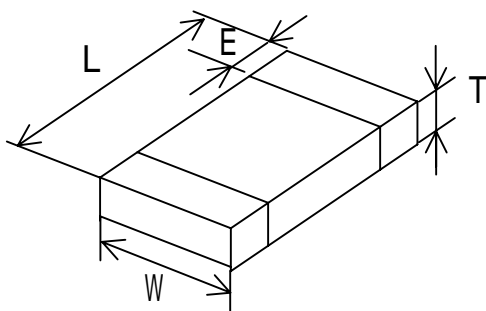


BCCL-2012E1-SERIES

PRODUCT DETAIL

Electrical Characteristics			Test Instruments
L	uH (Ref. Page 2~3)	TEST FREQ: MHz	<ul style="list-style-type: none"> •HP4291B RF IMPEDANCE / MATERIAL ANALYZER •HP4338A/B MILLIOHMMETER •Agilent 8720ES S-PARAMETER NETWORK ANALYZER •HP6632B SYSTEM DC POWER SUPPLY
Q	(Ref. Page 2~3)	(Ref. Page 8) TEST LEVEL: 100 mV	
SRF	MHz (Ref. Page 2~3)		
DCR	Ω (Ref. Page 2~3)		
IDC	mA (Ref. Page 2~3)		

SHAPES AND DIMENSIONS



Unit : mm

	1608	201209	201212	3216	4516	4532
L	1.6±0.15	2.0±0.2	2.0±0.2	3.2±0.2	4.5±0.25	4.5±0.25
W	0.8±0.15	1.25±0.2	1.25±0.2	1.6±0.2	1.6±0.2	3.2±0.25
T	0.8±0.15	0.9±0.2	1.25±0.2	1.1±0.2	1.6±0.2	1.5±0.25
E	0.3±0.2	0.5±0.3	0.5±0.3	0.5±0.3	0.6±0.4	0.6±0.4

BCCL-2012E1-SERIES

Part No.	Thickness (mm)	Inductance (μ H)	Q (min)	Freq. (MHz)	S. R. F(MHz) min	DCR(Ω) (Max.)	Rated Current
BCCL-2012E1-47NM	0.9 \pm 0.2	0.047 \pm 20%	20	50	320	0.20	300 mA
BCCL-2012E1-56NM	0.9 \pm 0.2	0.056 \pm 20%	20	50	300	0.20	300 mA
BCCL-2012E1-68NM	0.9 \pm 0.2	0.068 \pm 20%	20	50	280	0.20	300 mA
BCCL-2012E1-82NM	0.9 \pm 0.2	0.082 \pm 20%	20	50	275	0.20	300 mA
BCCL-2012E1-R10K	0.9 \pm 0.2	0.10 \pm 10%	20	25	255	0.30	250 mA
BCCL-2012E1-R12K	0.9 \pm 0.2	0.12 \pm 10%	20	25	250	0.30	250 mA
BCCL-2012E1-R15K	0.9 \pm 0.2	0.15 \pm 10%	20	25	230	0.40	250 mA
BCCL-2012E1-R18K	0.9 \pm 0.2	0.18 \pm 10%	20	25	210	0.40	250 mA
BCCL-2012E1-R22K	0.9 \pm 0.2	0.22 \pm 10%	20	25	195	0.50	250 mA
BCCL-2012E1-R27K	0.9 \pm 0.2	0.27 \pm 10%	20	25	170	0.50	250 mA
BCCL-2012E1-R33K	0.9 \pm 0.2	0.33 \pm 10%	20	25	165	0.50	250 mA
BCCL-2012E1-R39K	0.9 \pm 0.2	0.39 \pm 10%	25	25	155	0.60	200 mA
BCCL-2012E1-R47K	1.25 \pm 0.2	0.47 \pm 10%	25	25	140	0.60	200 mA
BCCL-2012E1-R56K	1.25 \pm 0.2	0.56 \pm 10%	25	25	130	0.70	150 mA
BCCL-2012E1-R68K	1.25 \pm 0.2	0.68 \pm 10%	25	25	120	0.80	150 mA
BCCL-2012E1-R82K	1.25 \pm 0.2	0.82 \pm 10%	25	25	115	1.00	150 mA
BCCL-2012E1-1R0K	0.9 \pm 0.2	1.0 \pm 10%	45	10	85	0.40	50 mA
BCCL-2012E1-1R2K	0.9 \pm 0.2	1.2 \pm 10%	45	10	75	0.50	50 mA
BCCL-2012E1-1R5K	0.9 \pm 0.2	1.5 \pm 10%	45	10	65	0.50	50 mA
BCCL-2012E1-1R8K	0.9 \pm 0.2	1.8 \pm 10%	45	10	60	0.60	50 mA
BCCL-2012E1-2R2K	0.9 \pm 0.2	2.2 \pm 10%	45	10	55	0.60	30 mA
BCCL-2012E1-2R7K	1.25 \pm 0.2	2.7 \pm 10%	45	10	50	0.70	30 mA
BCCL-2012E1-3R3K	1.25 \pm 0.2	3.3 \pm 10%	45	10	45	0.80	30 mA
BCCL-2012E1-3R9K	1.25 \pm 0.2	3.9 \pm 10%	45	10	44	0.90	30 mA
BCCL-2012E1-4R7K	1.25 \pm 0.2	4.7 \pm 10%	45	10	41	1.00	30 mA

BCCL-2012E1-SERIES

BCCL-2012E1-5R6K	1.25 ± 0.2	5.6 ± 10%	50	4	37	0.90	15 mA
BCCL-2012E1-6R8K	1.25 ± 0.2	6.8 ± 10%	50	4	34	1.00	15 mA
BCCL-2012E1-8R2K	1.25 ± 0.2	8.2 ± 10%	50	4	30	1.10	15 mA
BCCL-2012E1-10RK	1.25 ± 0.2	10.0 ± 10%	50	2	28	1.00	15 mA
BCCL-2012E1-12RK	1.25 ± 0.2	12.0 ± 10%	50	2	26	1.10	15 mA
BCCL-2012E1-15RK	1.25 ± 0.2	15.0 ± 10%	35	1	22	0.80	5 mA
BCCL-2012E1-18RK	1.25 ± 0.2	18.0 ± 10%	35	1	21	0.90	5 mA
BCCL-2012E1-22RK	1.25 ± 0.2	22.0 ± 10%	35	1	19	1.10	5 mA
BCCL-2012E1-33RK	1.25 ± 0.2	33.0 ± 10%	30	1	13	1.35	5 mA

* L & Q measured by an Agilent 4291B with an Agilent 16192A fixture

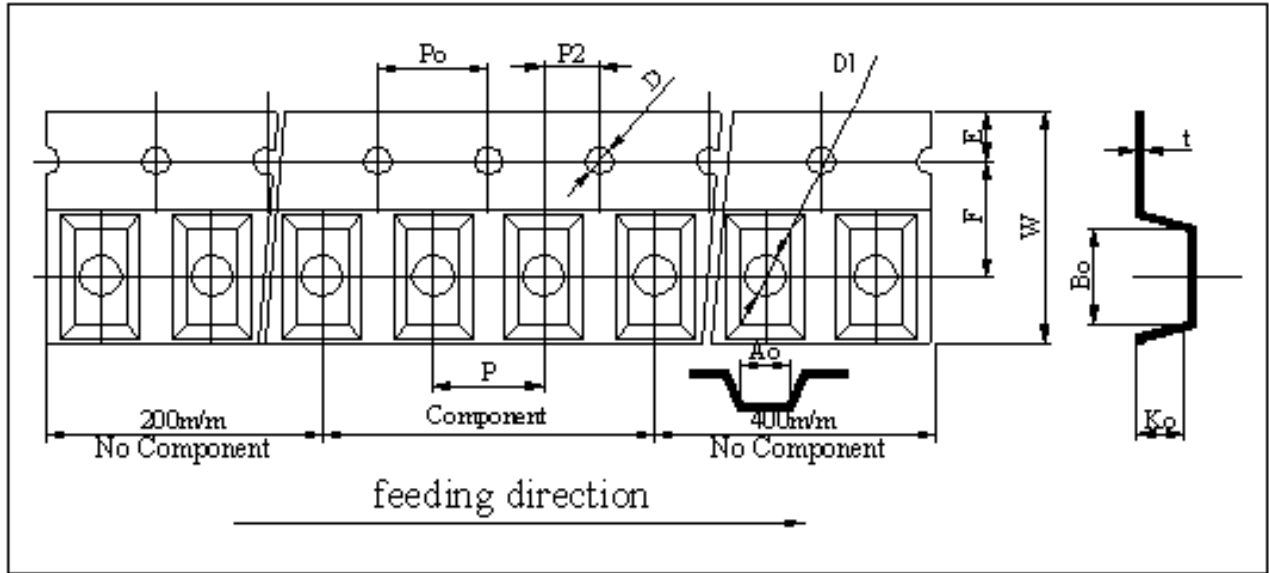
* DCR measured by an Agilent 4338 resistance meter

* SRF measured by an Agilent 4291B (1M ~ 1.8GHz) or Agilent 8720ES (50MHz ~ 20GHz)

BCCL-2012E1-SERIES

TAPE DIMENSIONS

Unit: mm

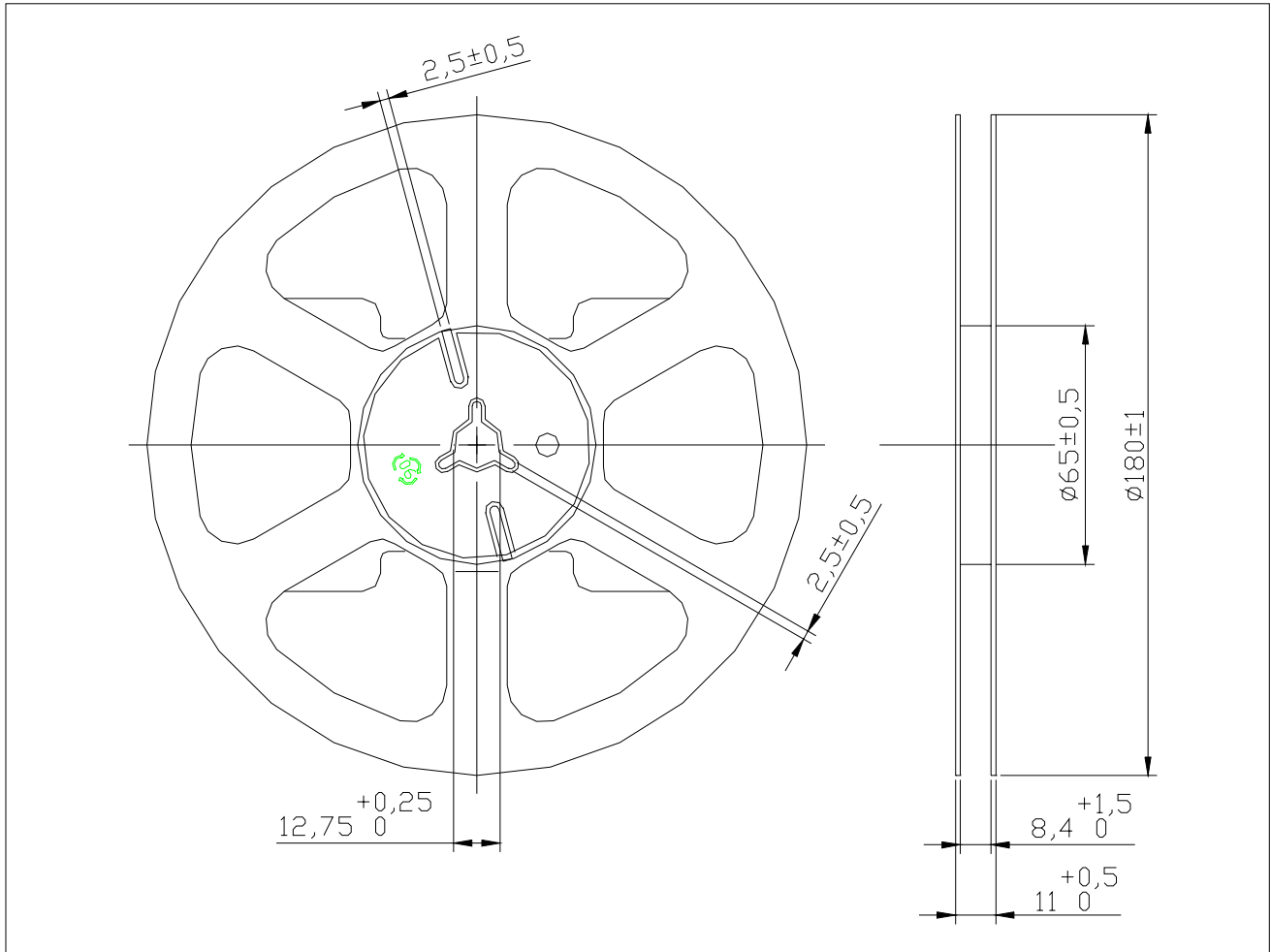


	453215	451616	322513	CBA3216	321611	201212	201209	160808	100505
W	12±0.1	11.9~12.3	7.9~8.3	7.9~8.3	7.9~8.3	7.9~8.3	7.9~8.3	7.9~8.3	7.9~8.3
P	8±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
F	5.5±0.05	5.5±0.1	3.5±0.05	3.5±0.05	3.5±0.05	3.5±0.05	3.5±0.05	3.5±0.05	3.5±0.05
D	1.55±0.05	1.55±0.1	1.55±0.05	1.55±0.05	1.55±0.05	1.50±0.05	1.50±0.05	1.50±0.05	1.50±0.05
D1	1.5~1.75	1.5~1.75	1.0~1.25	1.0~1.25	1.0~1.25	1.0~1.25	1.0~1.25	0.79±0.125	0.0±0
Po	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1	4.0±0.1
Po10	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2
P2	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05	2.0±0.05
Ao	3.66±0.1	1.829±0.1	2.57±0.1	1.78±0.1	1.88±0.1	1.42±0.1	1.42±0.1	1.0±0.1	0.65±0.1
Bo	4.95±0.1	4.849±0.1	3.4±0.1	3.4±0.1	3.5±0.1	2.24±0.1	2.24±0.1	1.8±0.1	1.18±0.1
Ko	1.83±0.1	1.829±0.1	1.32±0.1	1.04±0.1	1.27±0.1	1.04±0.1	1.04±0.01	1.0±0.1	0.62±0.1
t	0.23±0.1	0.242±0.1	0.25±0.1	0.229±0.013	0.23±0.1	0.25±0.1	0.25±0.1	0.254±0.1	0.23±0.1
Pcs / Reel	1000 pcs	2000 pcs	2000 pcs	3000 pcs	3000 pcs	3000 pcs	4000 pcs	4000 pcs	4000 pcs

BCCL-2012E1-SERIES

REEL DIMENSIONS

Unit: mm



Reel Packaging Quantity									
PART SIZE		1005	1608	201209	201212	3216	3225	4516	4532
7" REEL	Qty. (pcs)	4,000	4,000	4,000	3,000	3,000	2,000	2,000	1,000
13" REEL		10,000	10,000	10,000	10,000	6,000	5,000	5,000	2,500
BULK		20,000	20,000	20,000	20,000	20,000	10,000	10,000	10,000

BCCL-2012E1-SERIES

RELIABILITY AND TEST CONDITION

Stress	Performance	Test Condition
Leaching	The chip should not crack ; More than 90% of the terminal electrode should be covered with solder , free from defects, chip body should not exposed.	1.Solder: Alpha Sn100 2.Solder Temp: 260 ±5 3.Flux: Rosin 4.Dip time: 10 ±1 sec
Solderability 1 (IR Re-flow test)	1.Sn cover area need to over half thickness of chip 2.Chip shift distance under 50% of width 3.No short , open ,...etc defect symptom	1.Solder: M705-GRN360-K2-V Sn96.5/Ag3/Cu0.5 2.General:135/135/195/235 3.100% TIN:155/155/220/265
Solderability 2	More than 90% of the terminal electrode should be covered with new solder	1.Solder: Alpha Sn100 2.Solder Temp.:230 ±5 3.Flux: Rosin 4.Dip time: 4±1 sec
Terminal Strength	The terminal electrode should not break off nor the ferrite damaged	100505>0.2kgt , 160808>0.3kgt , 201209>0.6kgt , 201212>0.6kgt , 321611>1.0kgt , 322513>1.0kgt , 451616>1.0kgt , 453215>1.5kgt , BCCBA3216>1.2kgt ; pulling time:30 ±5 sec
Bending Strength	The ferrite should not be damaged by force applied on the right	100505>0.2kgf , 160808>0.3kgf , 201209>1.0kgf , 201212>1.0kgf , 321611>2.0kgf , 322513>2.5kgf , 451616>2.5kgf , 453215>2.5kgf , BCCBA3216>2.0kgf
Flexure Strength	No mechanical damage shall be noticed even when the board is bent 2 mm (0.079 inches)	1.At ambient temperature & Humidity 2.To bend 2 mm
Thermal Shock	1.No mechanical damage 2.Inductance should be within ±5% of the initial value 3.Q value should be within ±30% of the initial value 4.Impedance value should be	1.Temperature:-40 ~ 85 For 30 minutes each 2.Cycle: 100 cycles 3.Measurement: At ambient temperature 24 hours After test completion

BCCL-2012E1-SERIES

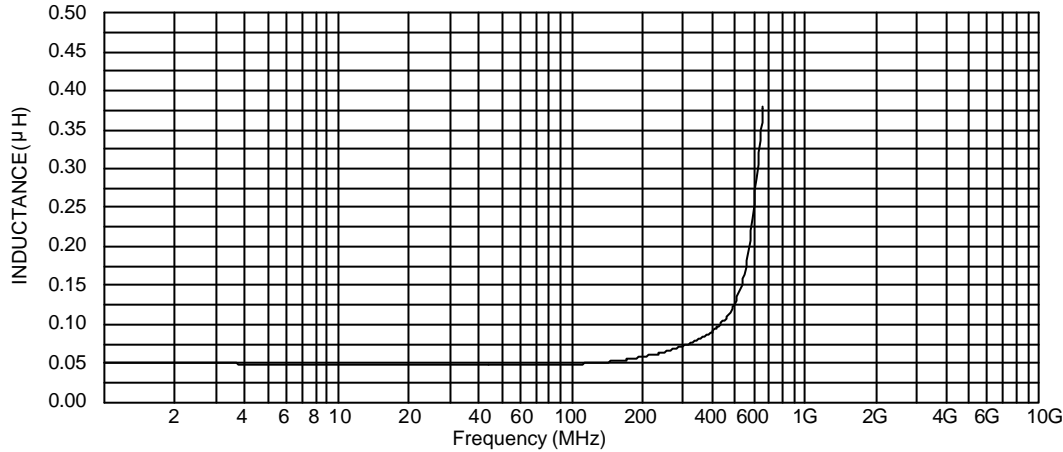
	within $\pm 20\%$ of the initial value	
Temperature Cycling	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1. Temperature:-40~125 2. Cycle: 100 cycles 3. Measurement: At ambient temperature 24 hours After test completion
Biased Humidity	<ol style="list-style-type: none"> 1.No mechanical damage 2.Inductance should be within $\pm 5\%$ of the initial value 3.Q value should be within $\pm 30\%$ of the initial value 4.Impedance value should be within $\pm 20\%$ of the initial value 	<ol style="list-style-type: none"> 1.Temperature: 40 2.Humidity: 85 % RH 3.Applied current: Full rated current 4.Testing time: 1000 hrs 5. Measurement: At ambient temperature 24 hours After test completion
Rated Current	<ol style="list-style-type: none"> 1.BCCB / BCCL / BCCLH product Surface temperature below room temperature plus 10 2.High current DC power (ES) product surface temp. below room temperature plus 40 	<ol style="list-style-type: none"> 1.At ambient temperature & humidity 2.Testing time:5 minutes (under full rated current)

BCCL-2012E1-47NM

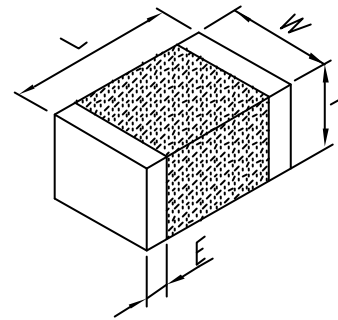
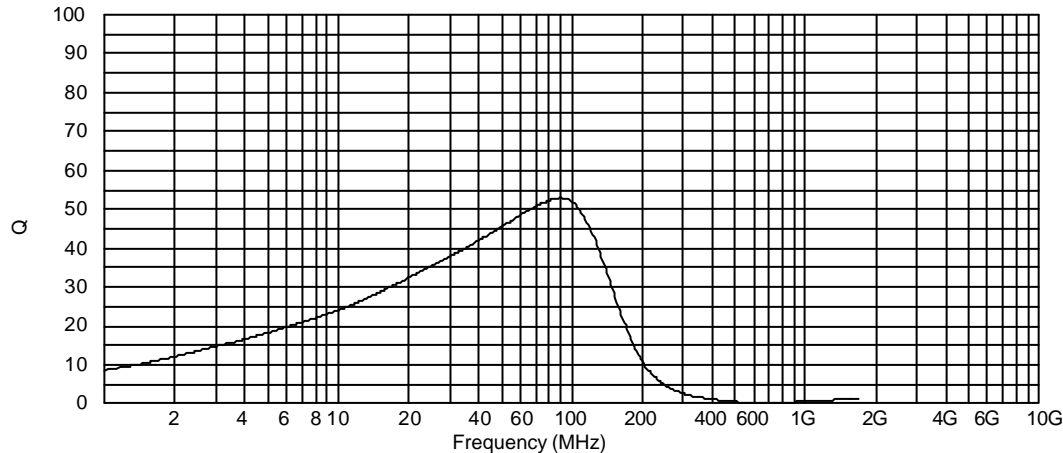
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.047	20	0.20	320	300

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

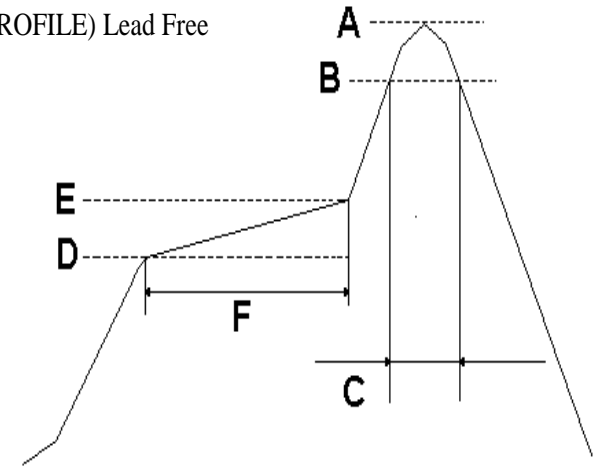
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

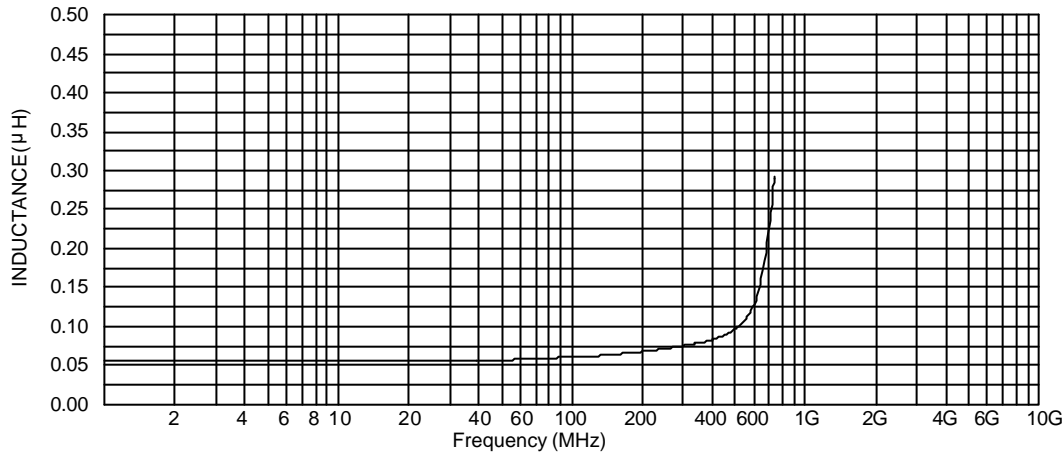


BCCL-2012E1-56NM

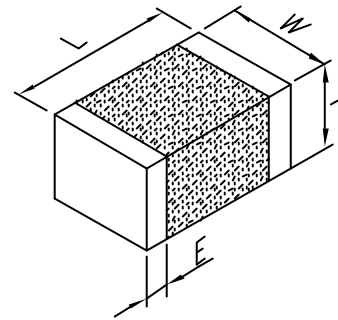
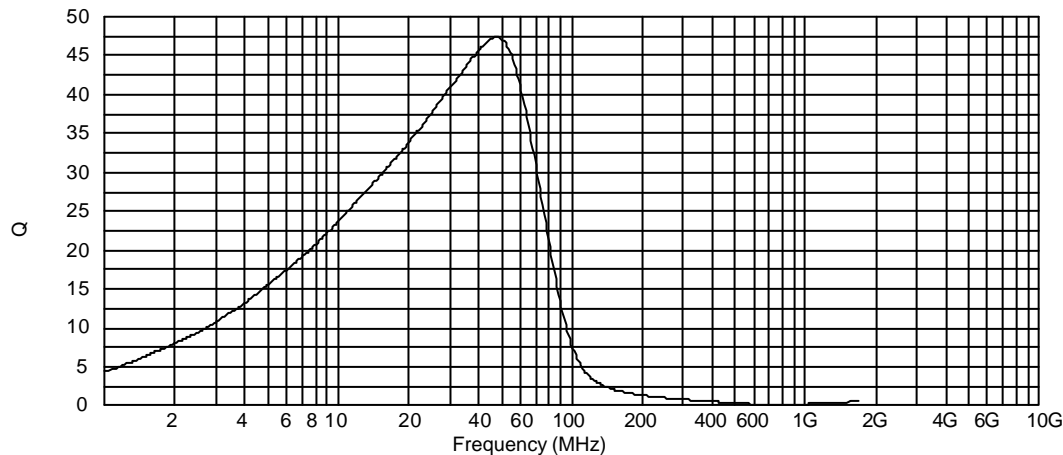
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.056	20	0.2	300	300

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

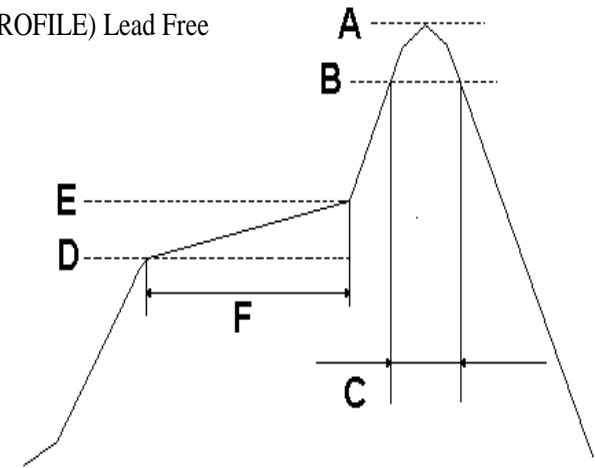
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

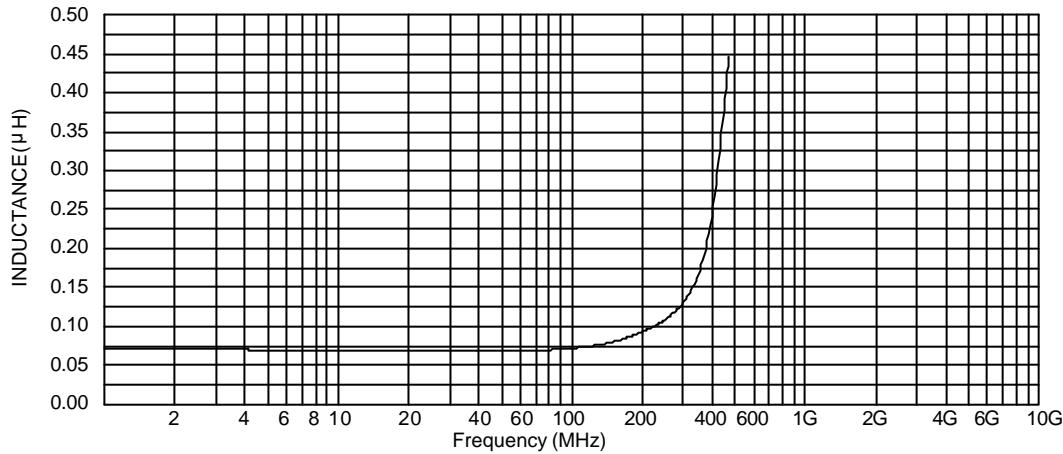


BCCL-2012E1-68NM

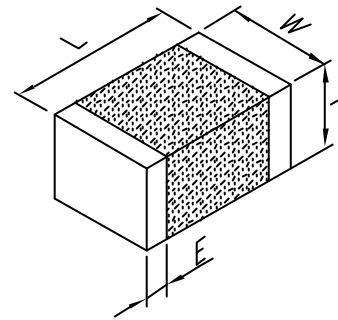
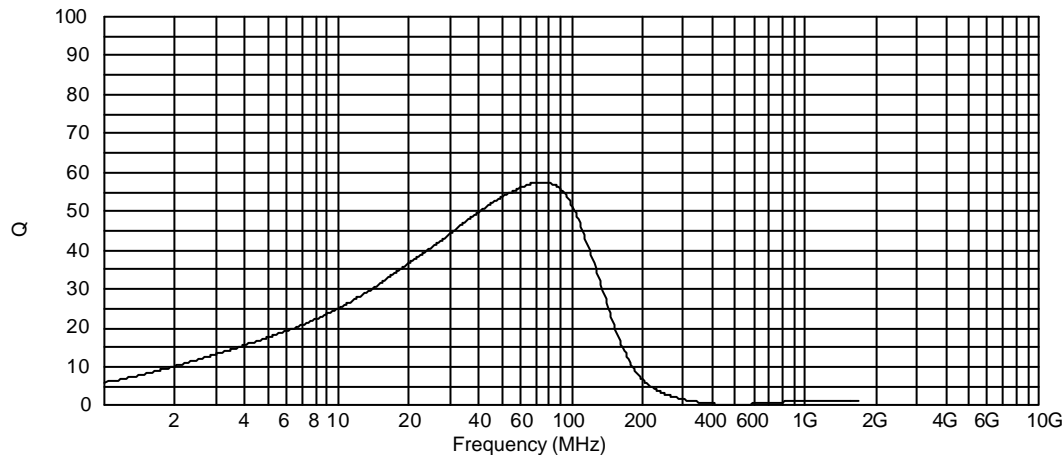
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.068	20	0.20	280	300

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

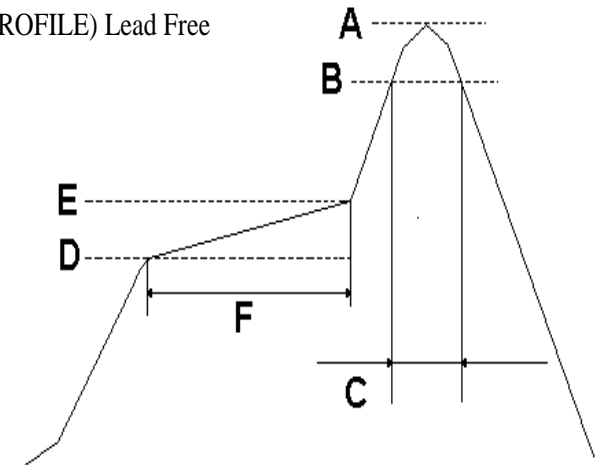
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

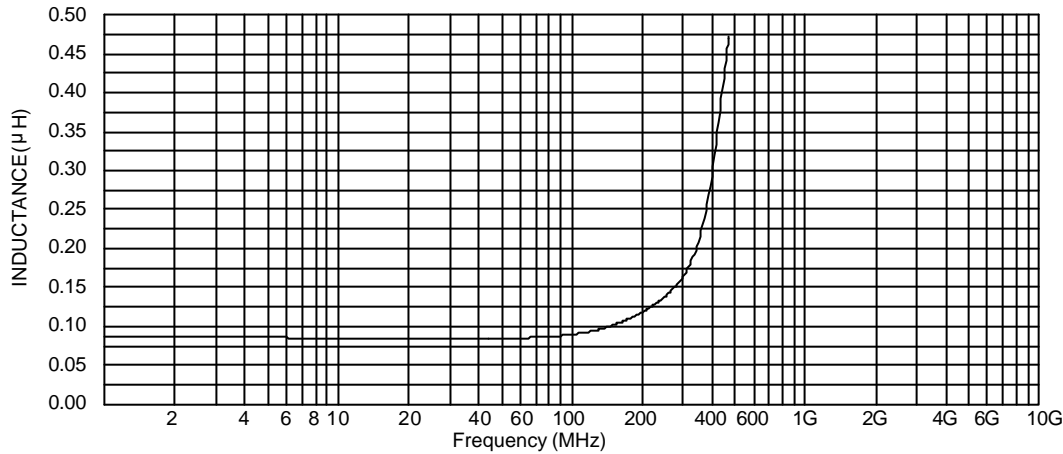


BCCL-2012E1-82NM

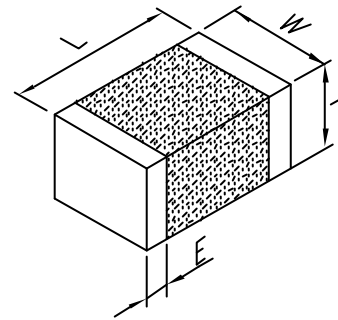
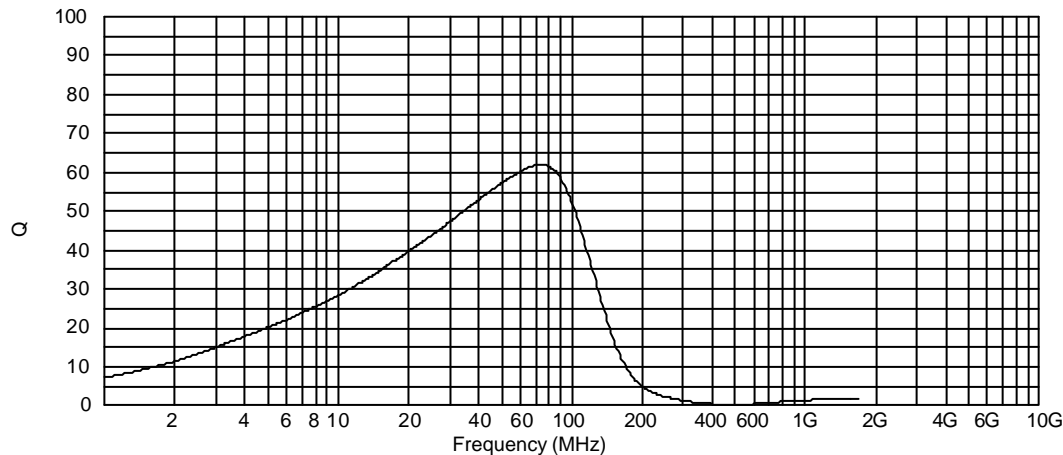
ELECTRICAL CHARACTERISTICS:

L@50MHz ($\mu\text{H} \pm 20\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.082	20	0.2	275	300

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

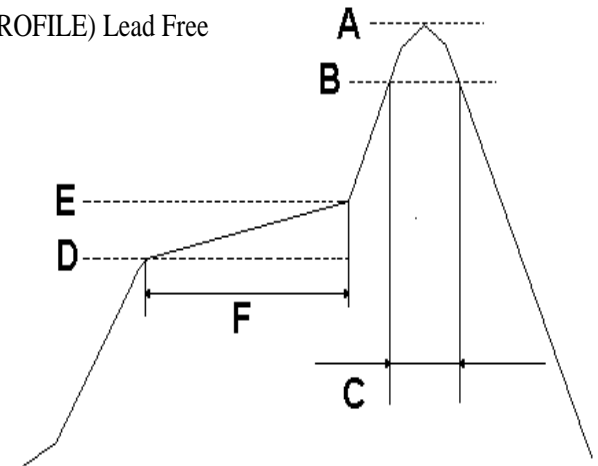
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

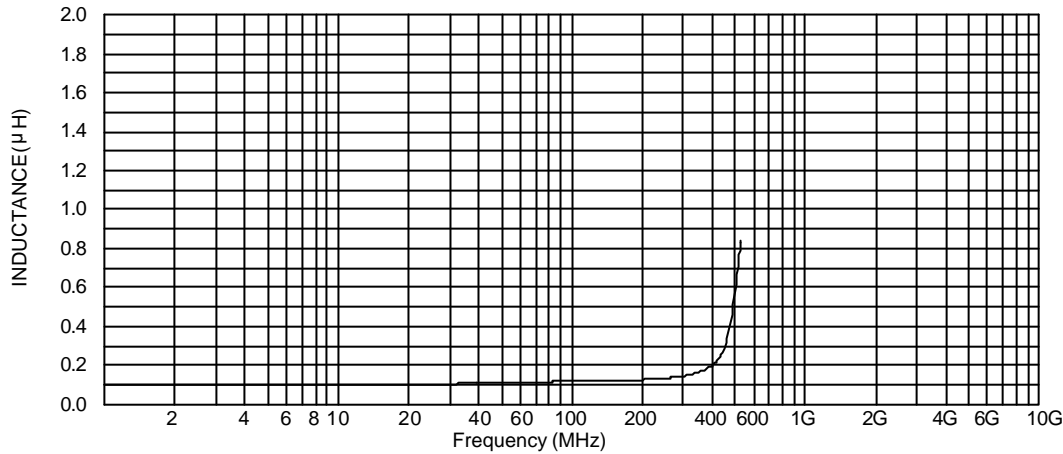


BCCL-2012E1-R10K

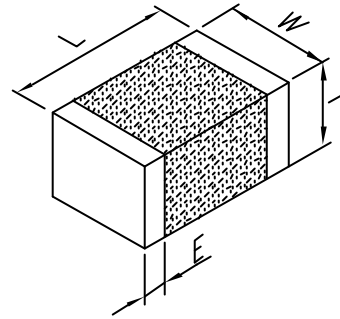
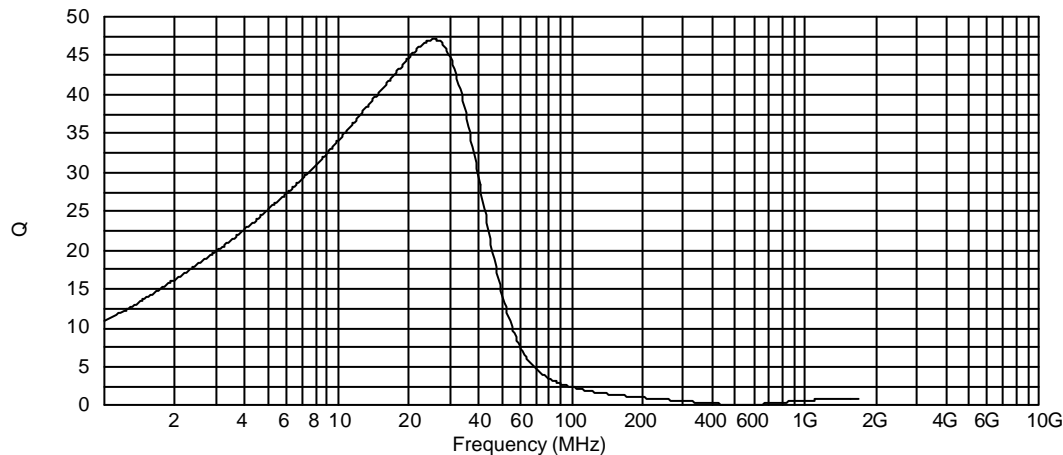
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.1	20	0.3	255	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

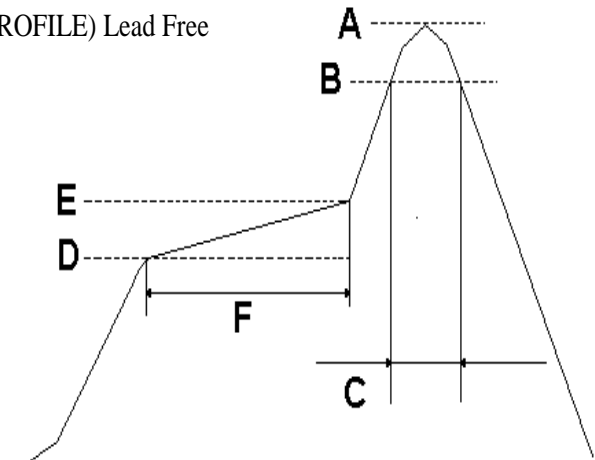
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

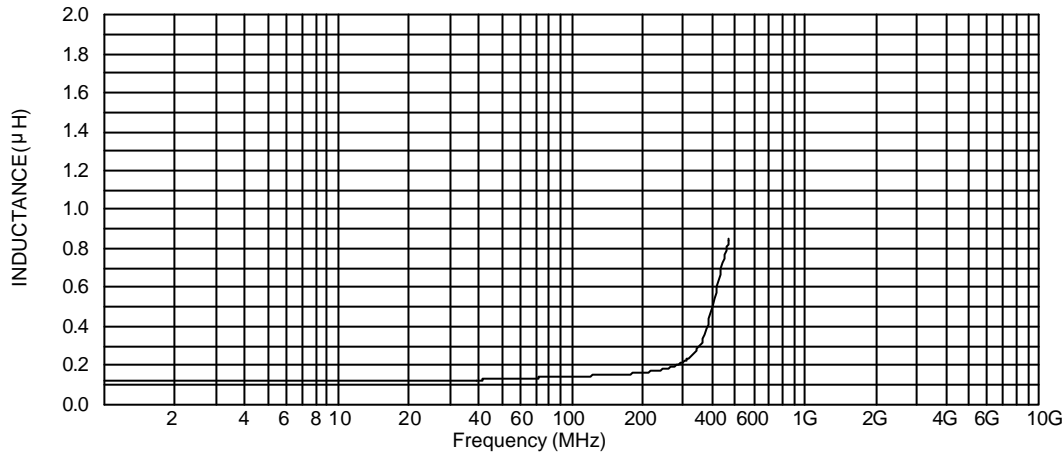


BCCL-2012E1-R12K

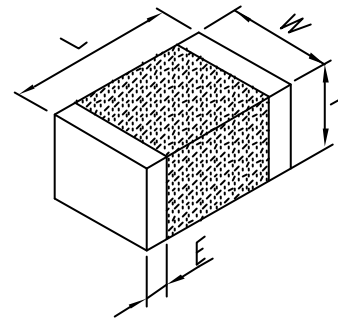
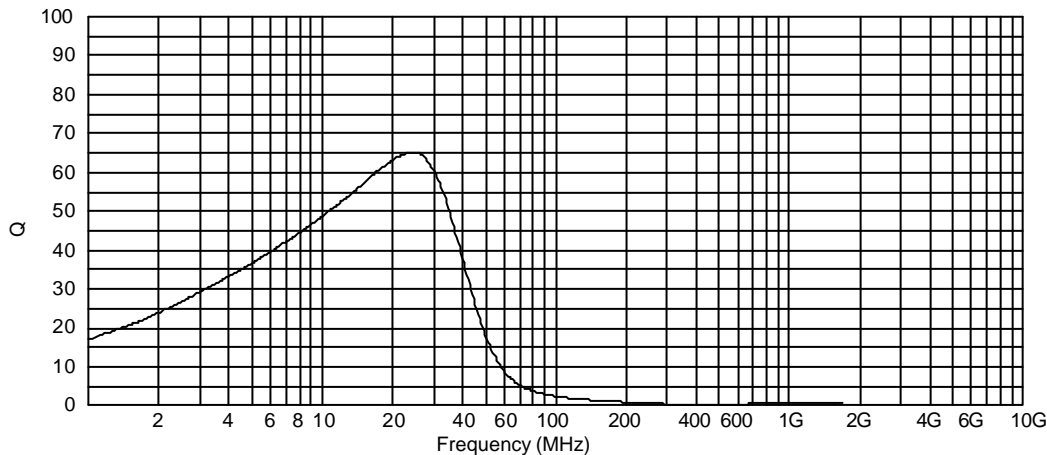
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.12	20	0.30	250	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

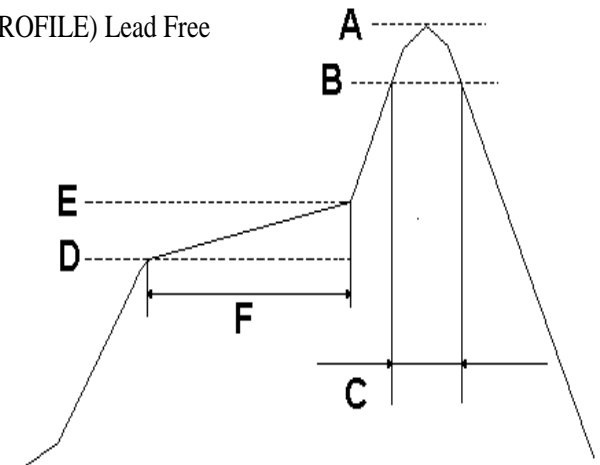
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

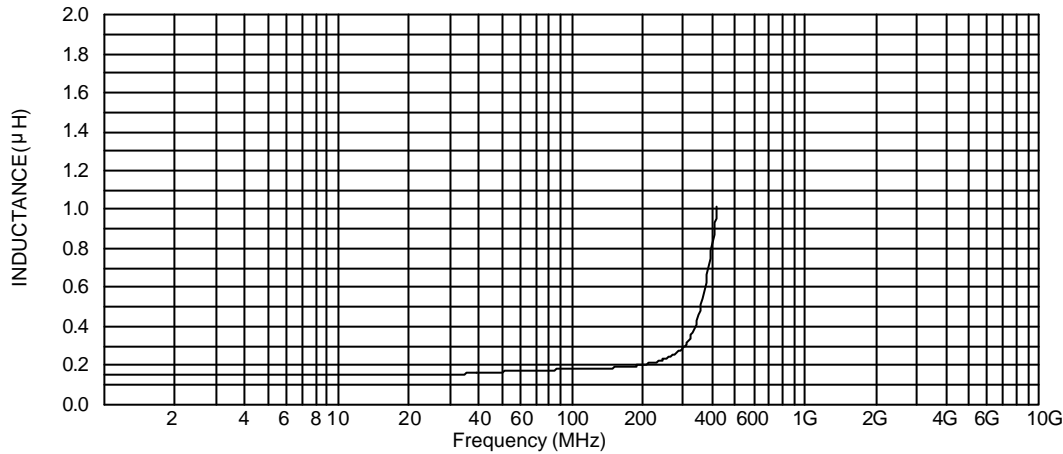


BCCL-2012E1-R15K

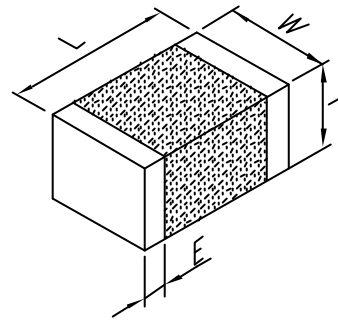
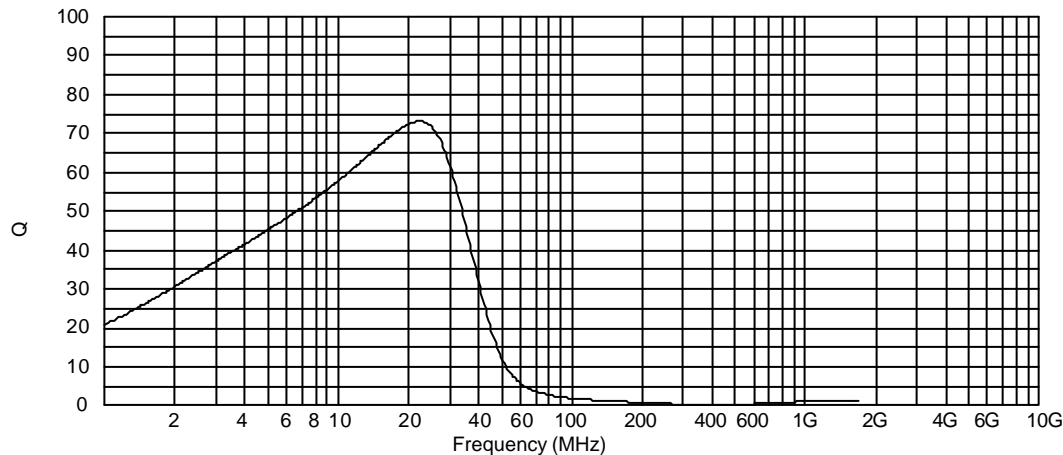
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.15	20	0.4	230	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

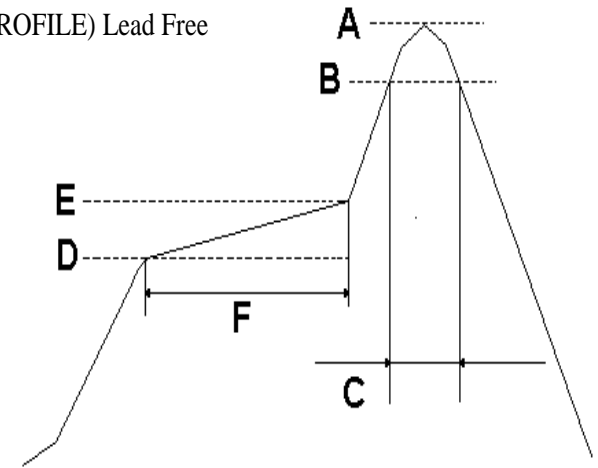
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

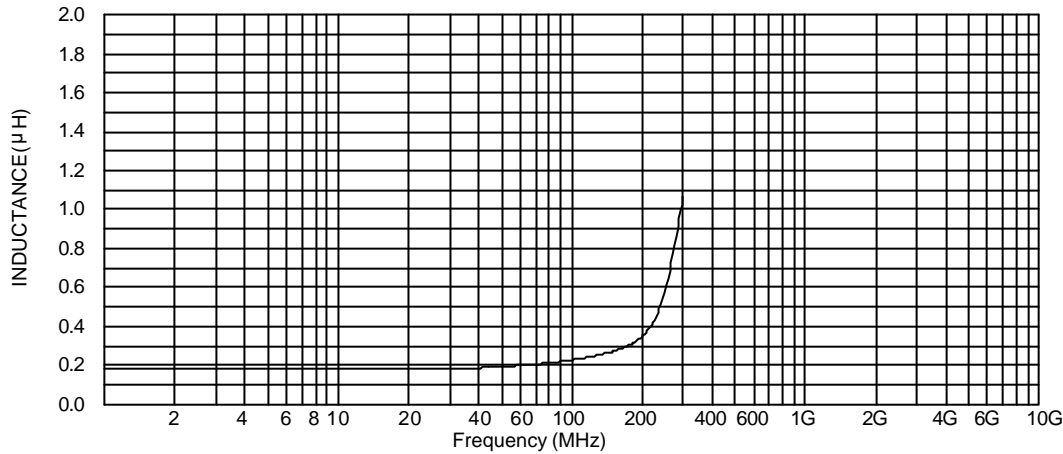


BCCL-2012E1-R18K

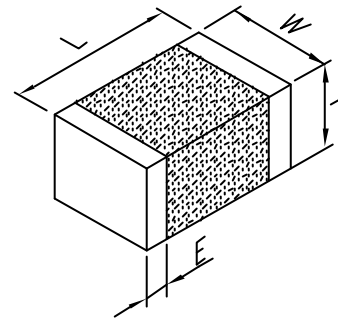
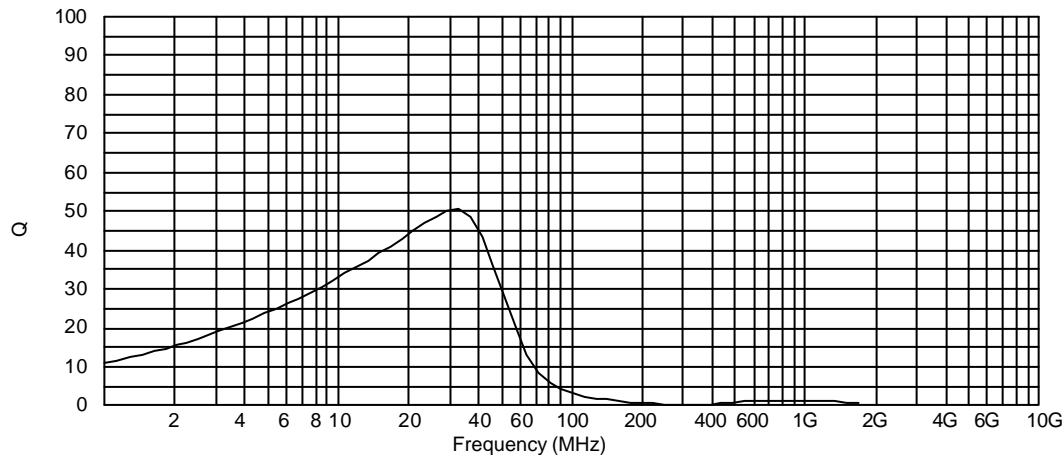
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.18	20	0.4	210	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

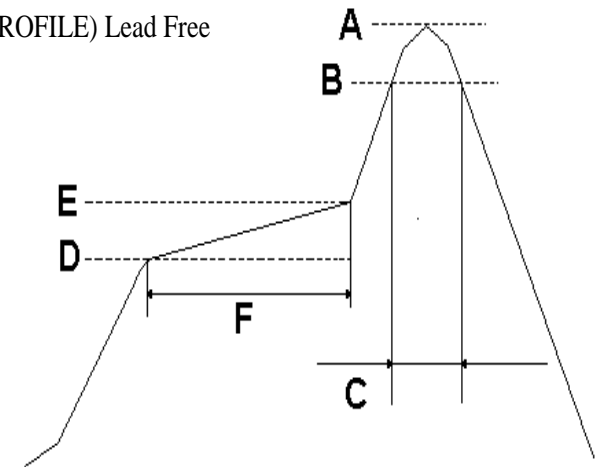
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

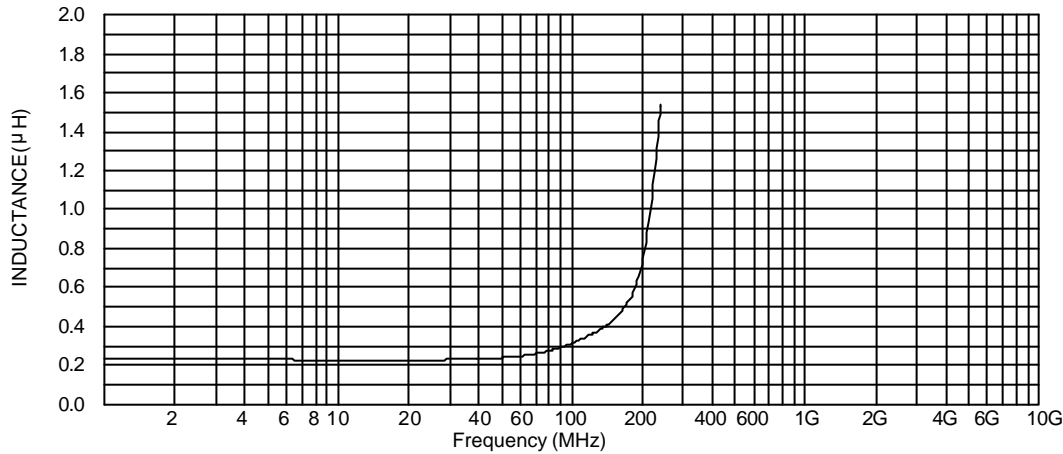


BCCL-2012E1-R22K

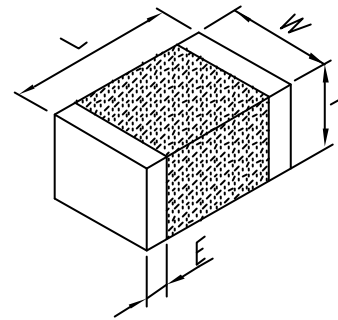
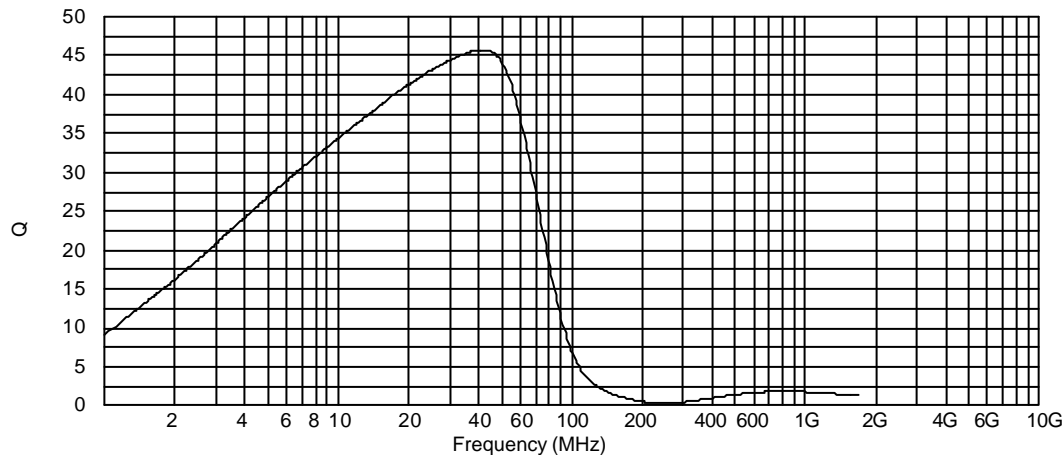
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.22	20	0.5	195	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

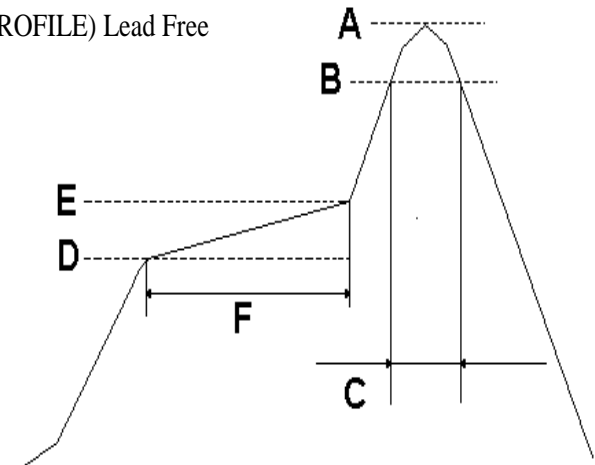
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

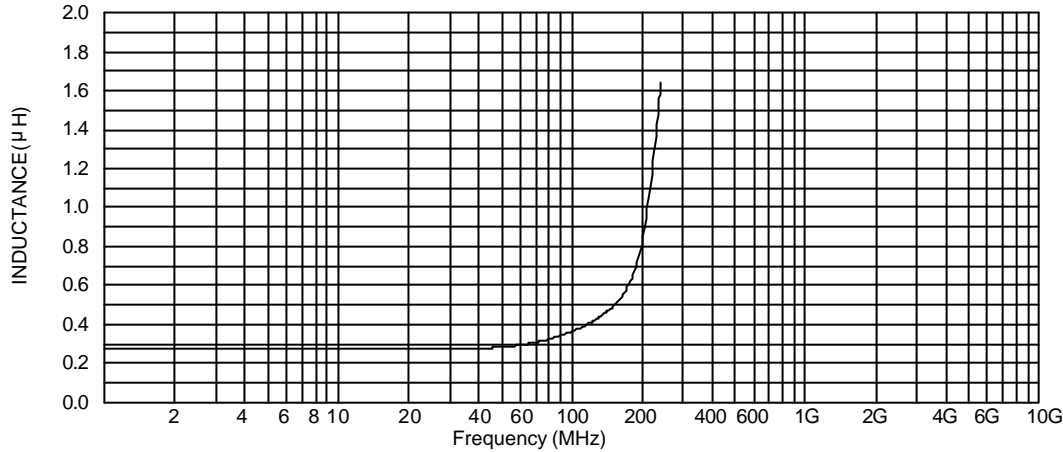


BCCL-2012E1-R27K

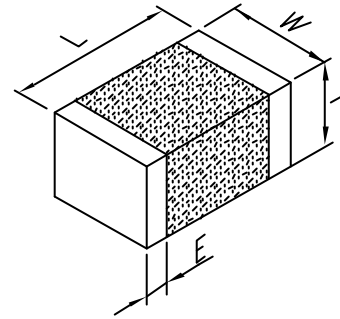
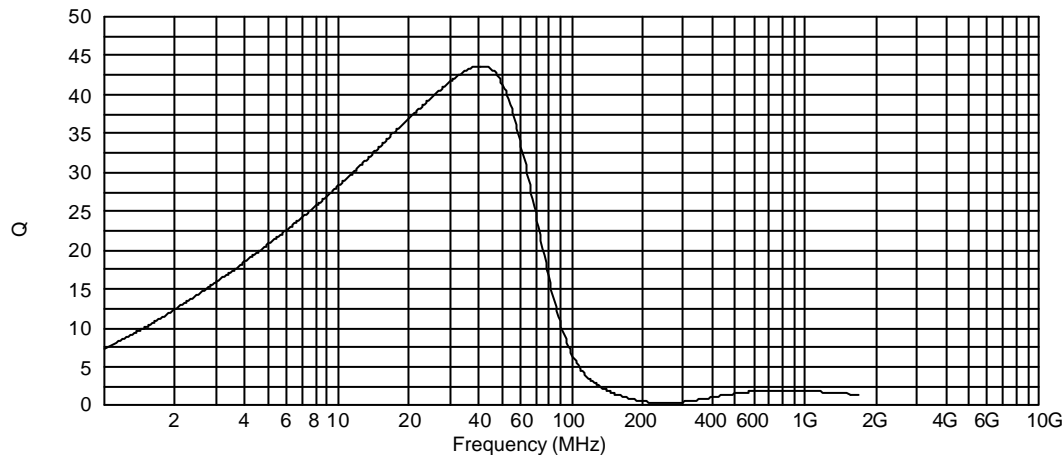
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.27	20	0.5	170	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

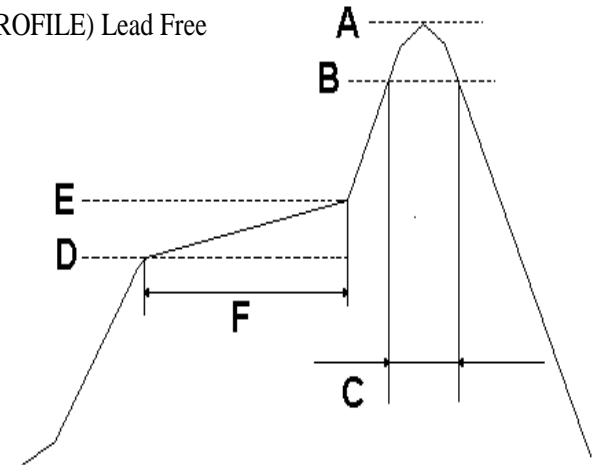
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 \pm 5/-0
B	230
C	30 \pm 10 sec
D	150
E	180
F	90 \pm 30sec

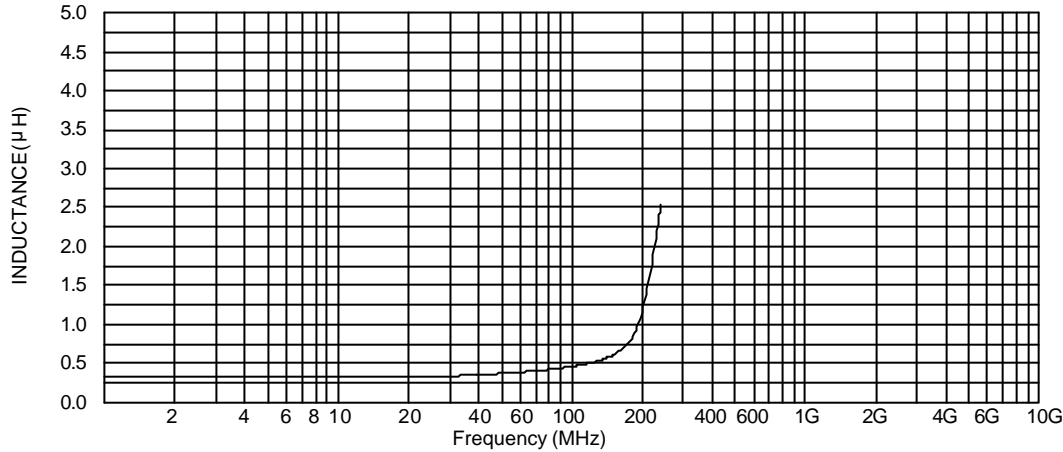


BCCL-2012E1-R33K

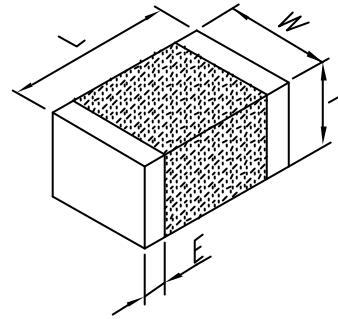
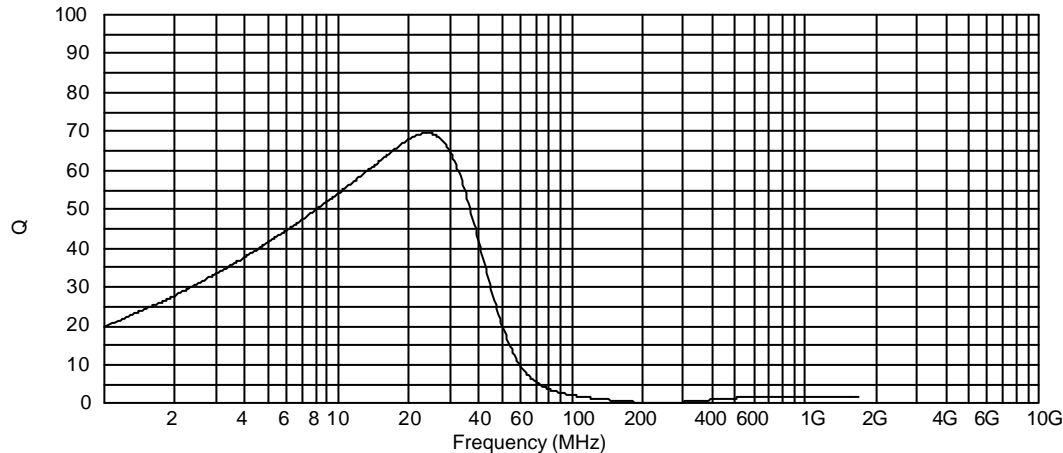
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.33	20	0.5	165	250

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

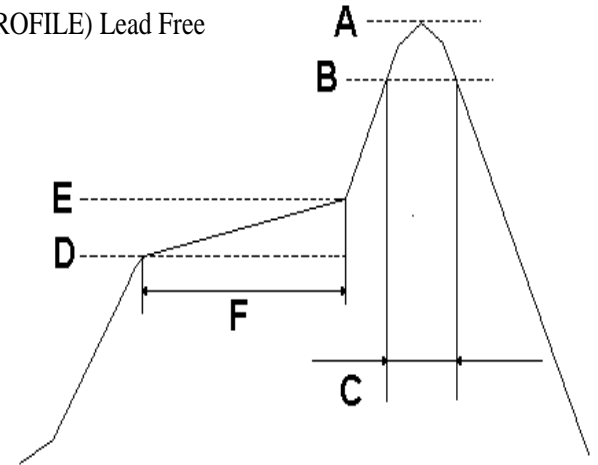
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	$30 \pm 10 \text{ sec}$
D	150
E	180
F	$90 \pm 30 \text{ sec}$

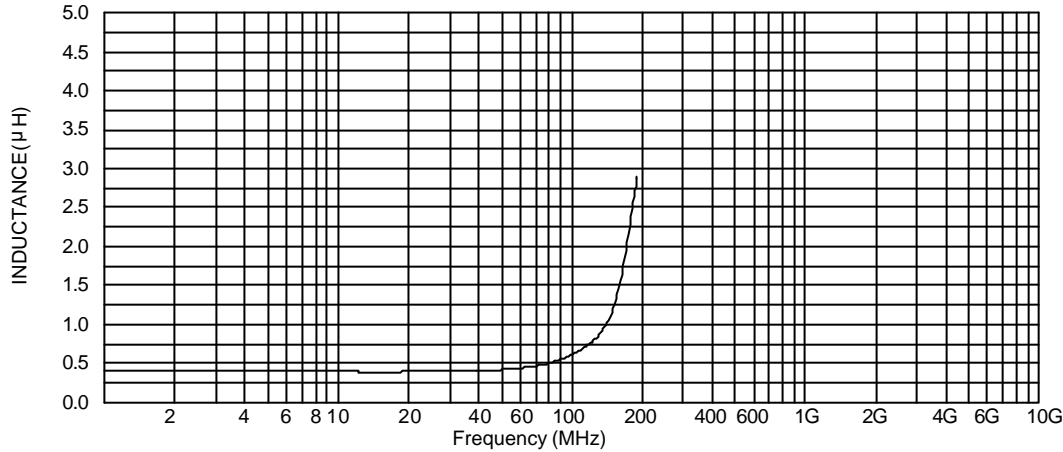


BCCL-2012E1-R39K

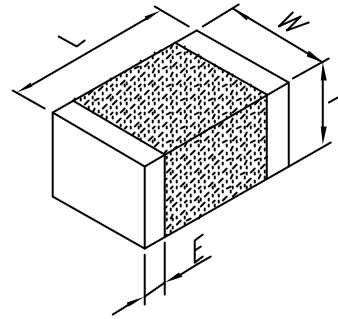
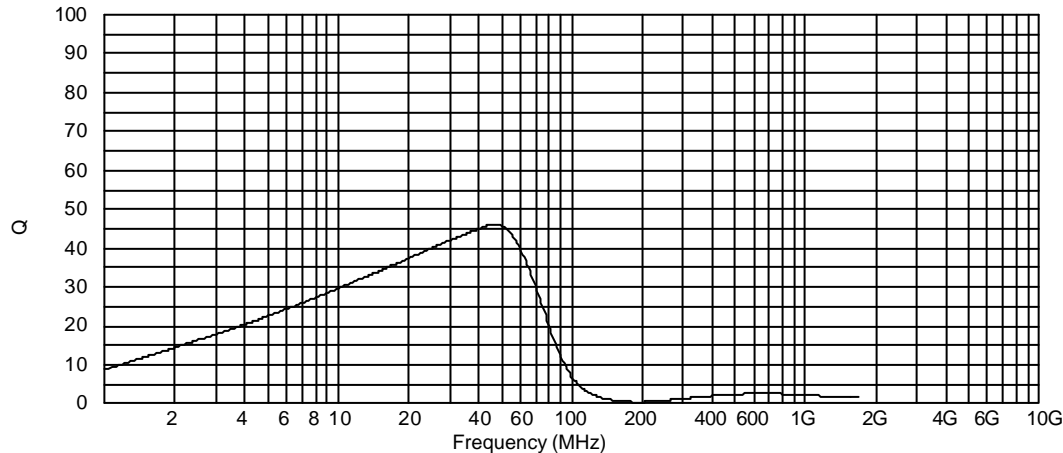
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.39	25	0.6	155	200

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

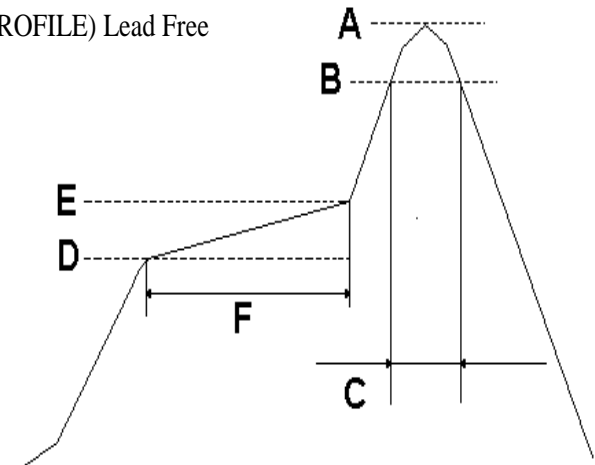
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

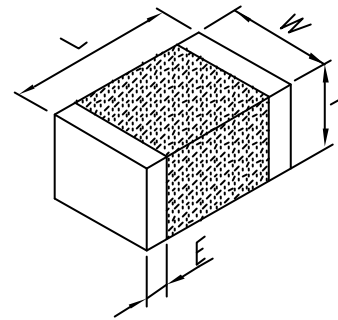
A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>



BCCL-2012E1-R47K

ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.47	25	0.6	140	200



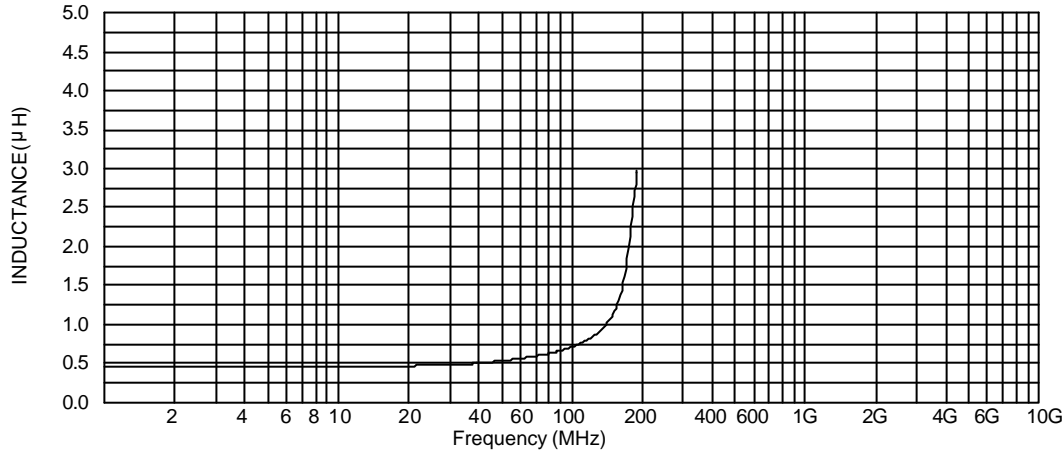
PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

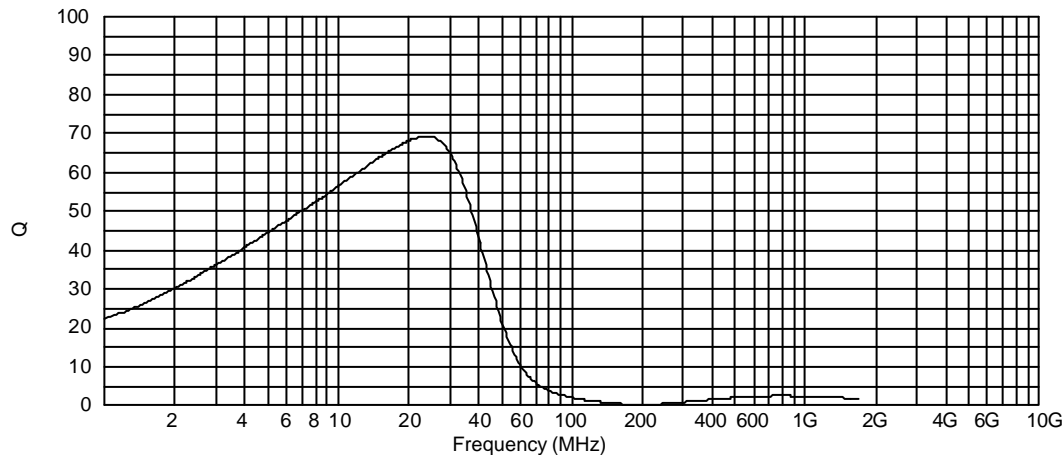
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

INDUCTANCE vs. FREQUENCY



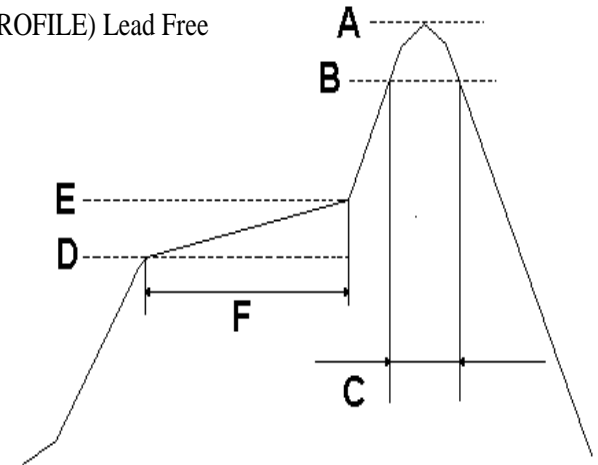
Q vs. FREQUENCY CHARACTERISTICS



Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 \pm 5/-0
B	230
C	30 \pm 10 sec
D	150
E	180
F	90 \pm 30sec

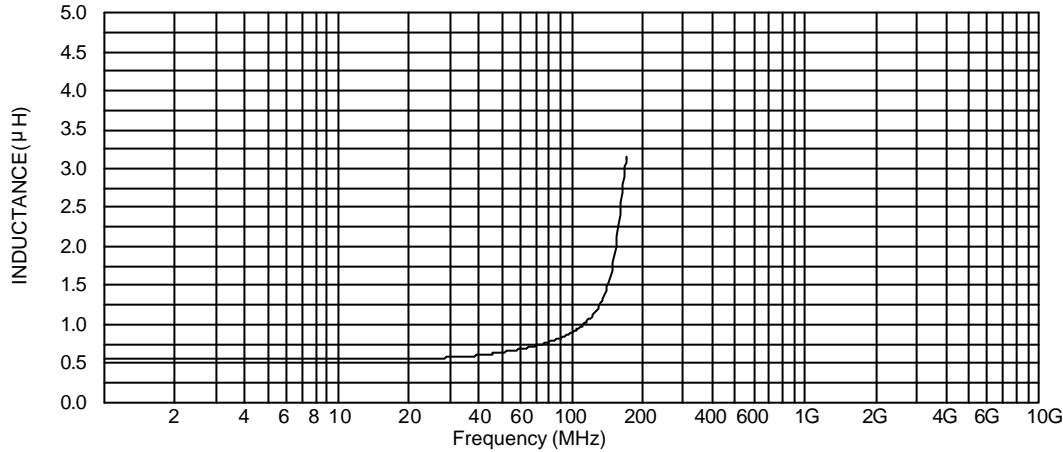


BCCL-2012E1-R56K

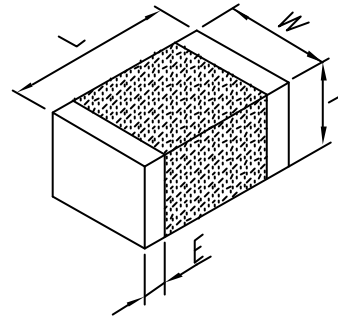
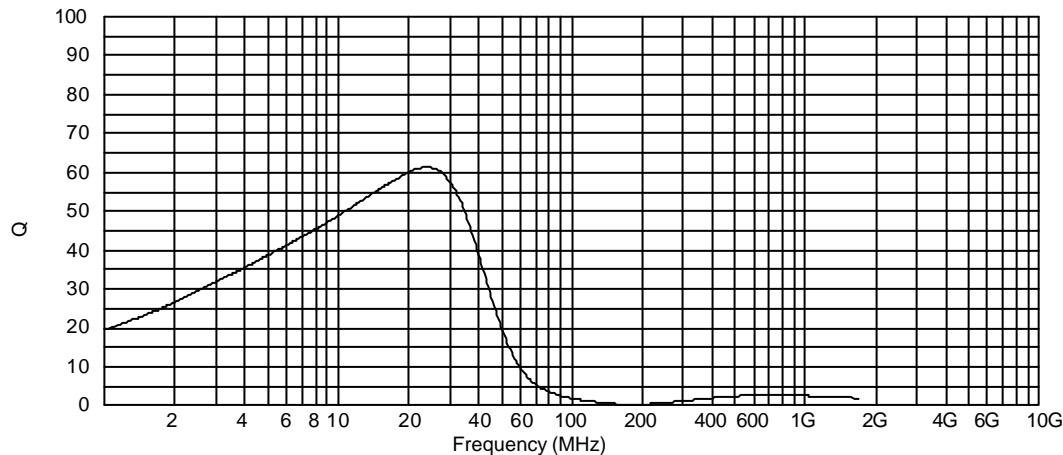
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.56	25	0.7	130	150

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

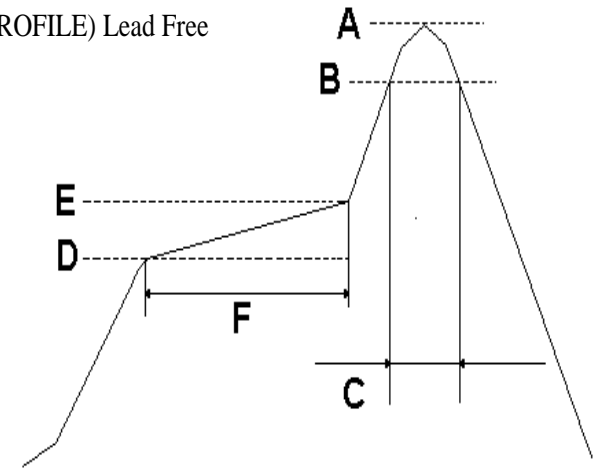
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

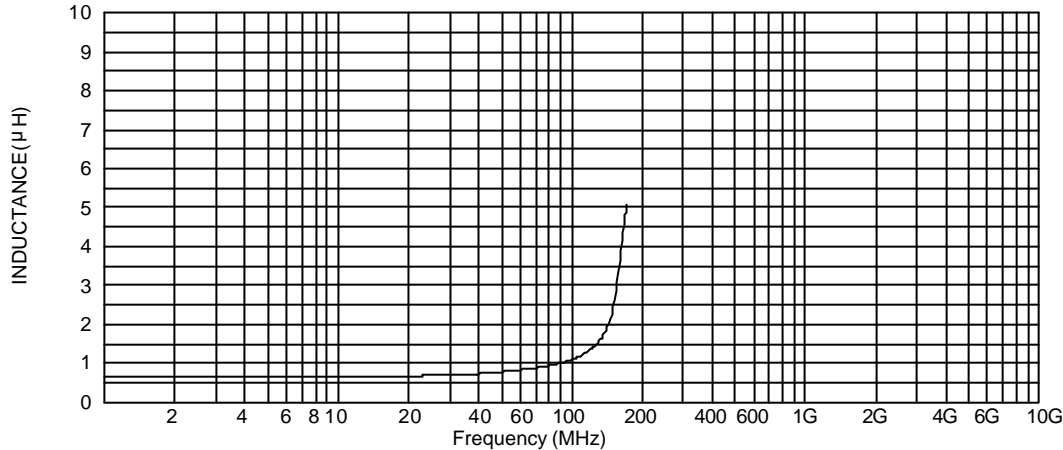


BCCL-2012E1-R68K

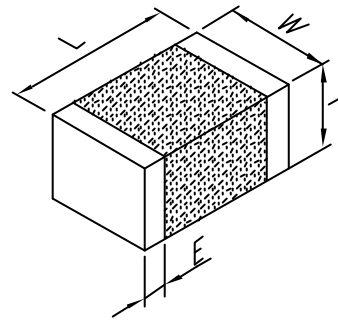
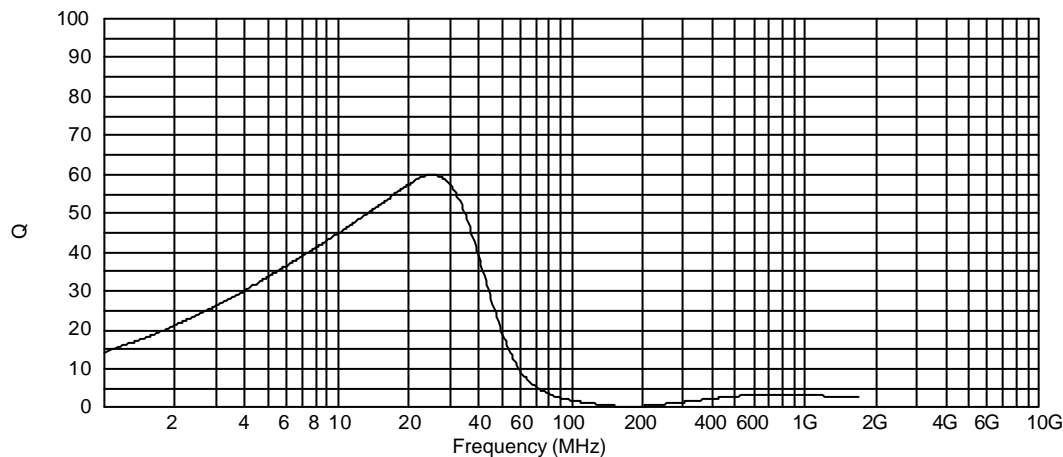
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.68	25	0.8	120	150

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

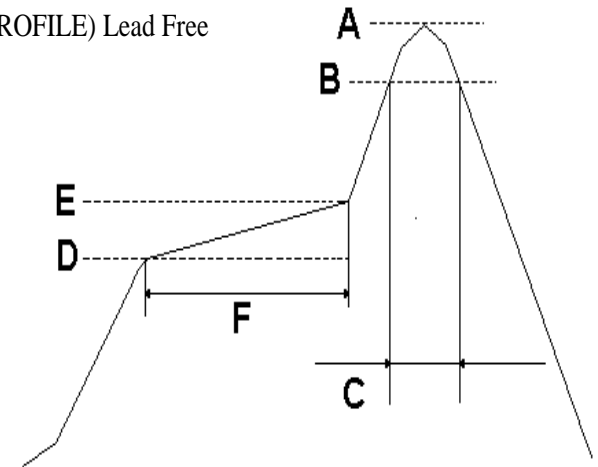
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec

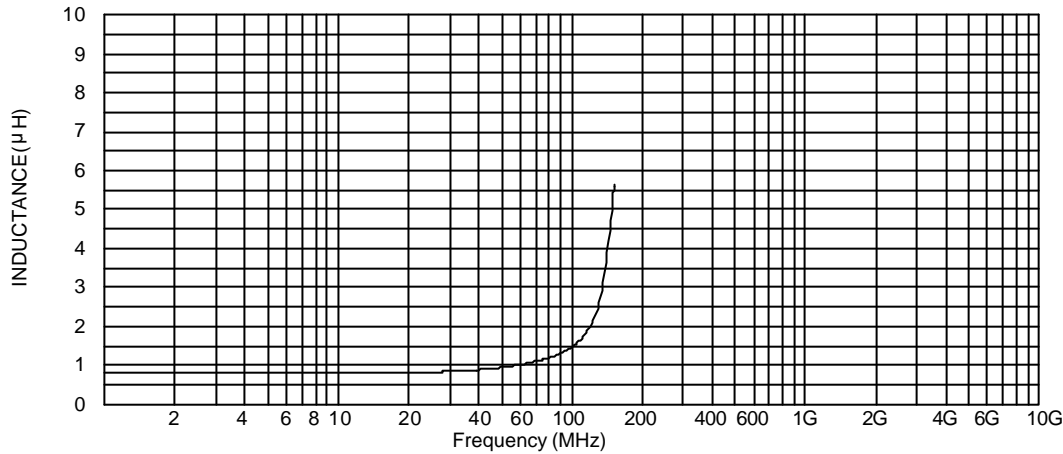


BCCL-2012E1-R82K

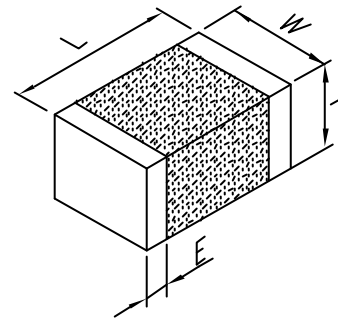
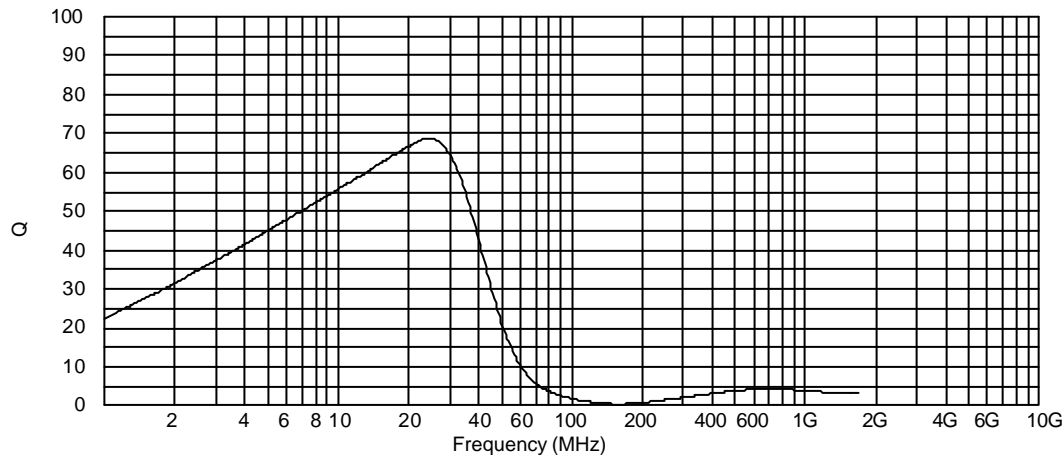
ELECTRICAL CHARACTERISTICS:

L@25MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
0.82	25	1.0	115	150

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

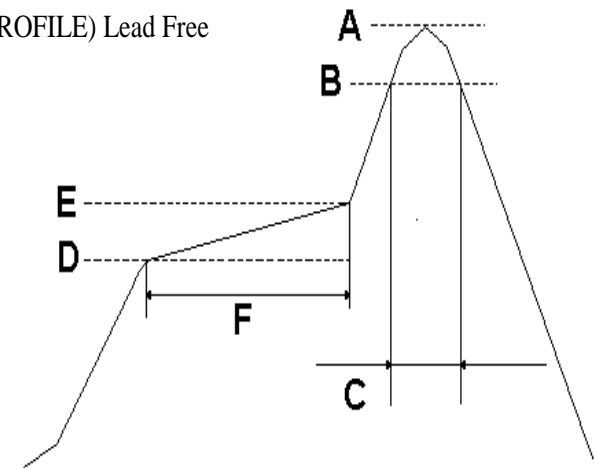
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

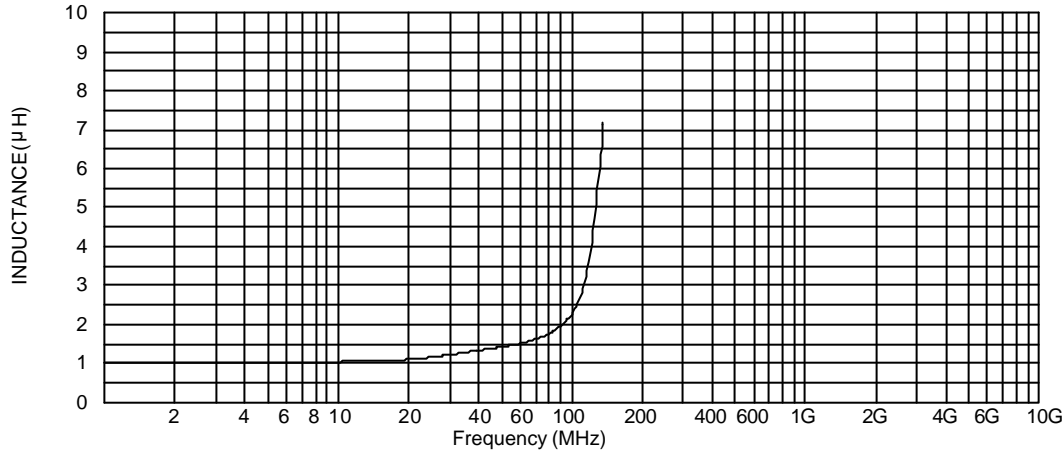


BCCL-2012E1-1R0K

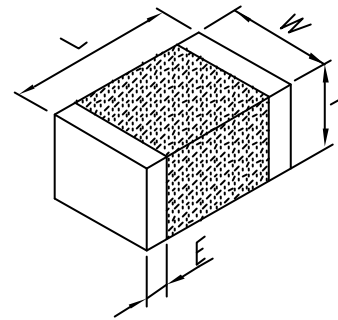
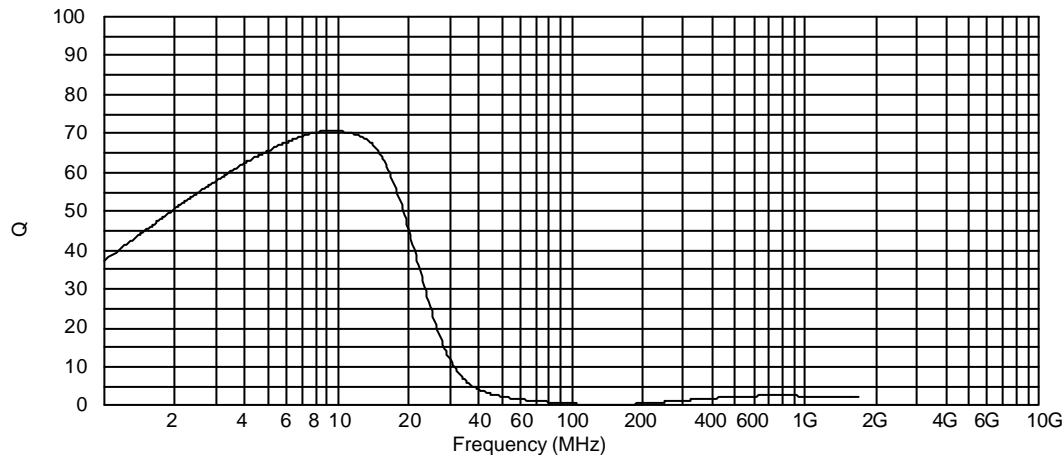
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.0	45	0.4	85	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

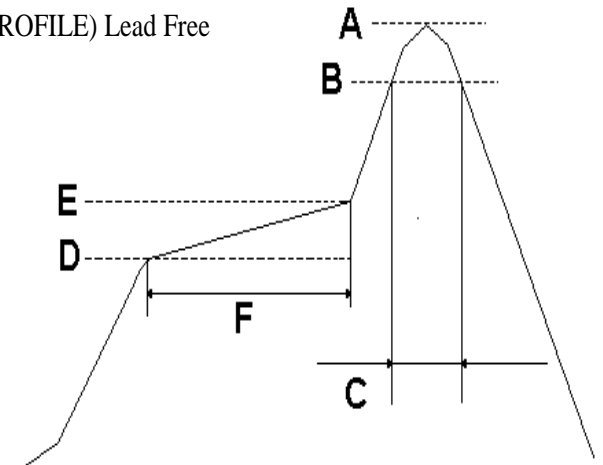
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 \pm 5/-0
B	230
C	30 \pm 10 sec
D	150
E	180
F	90 \pm 30sec

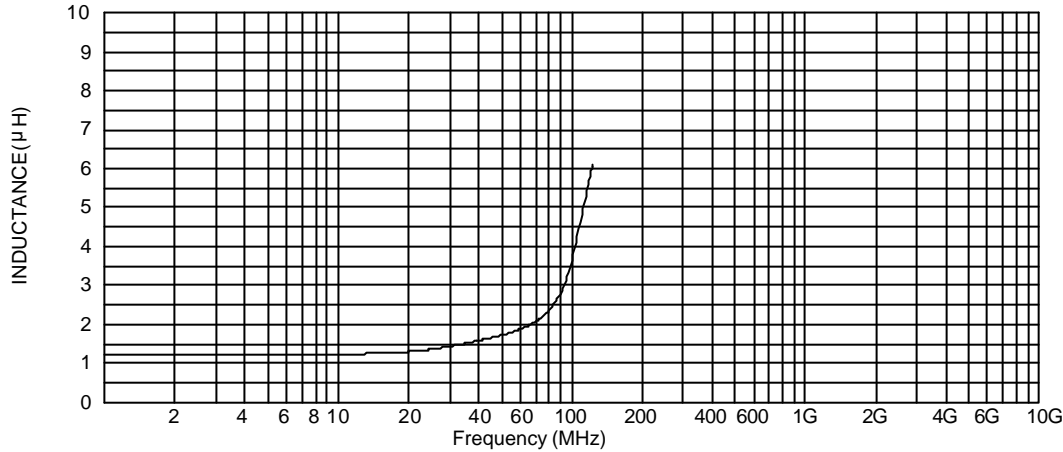


BCCL-2012E1-1R2K

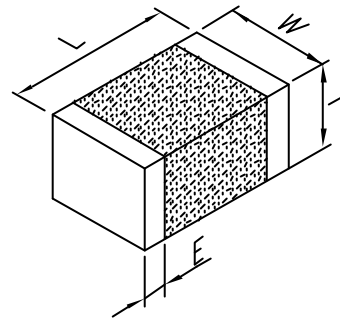
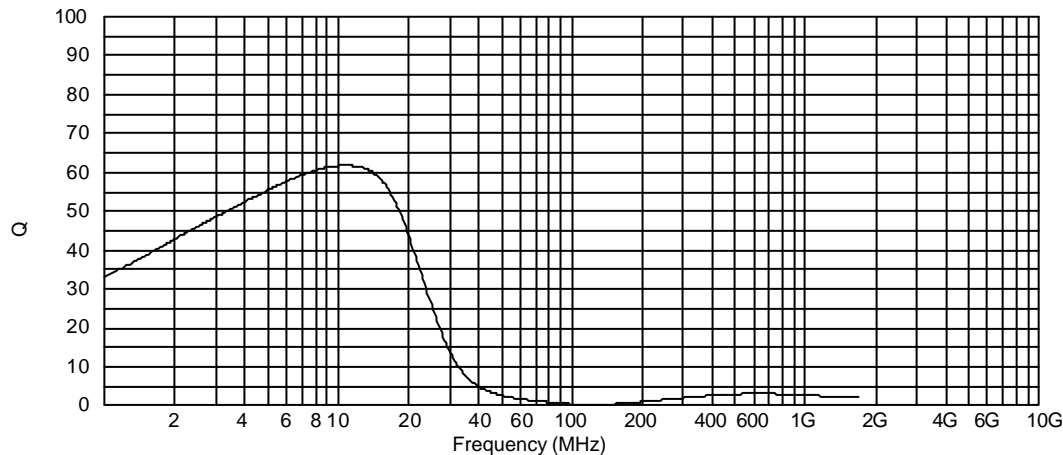
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.2	45	0.5	75	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

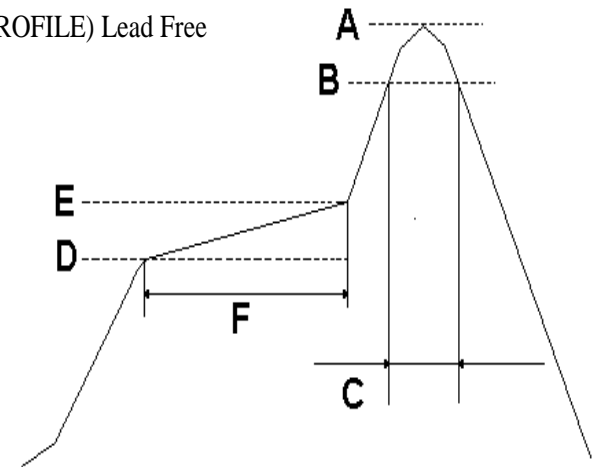
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

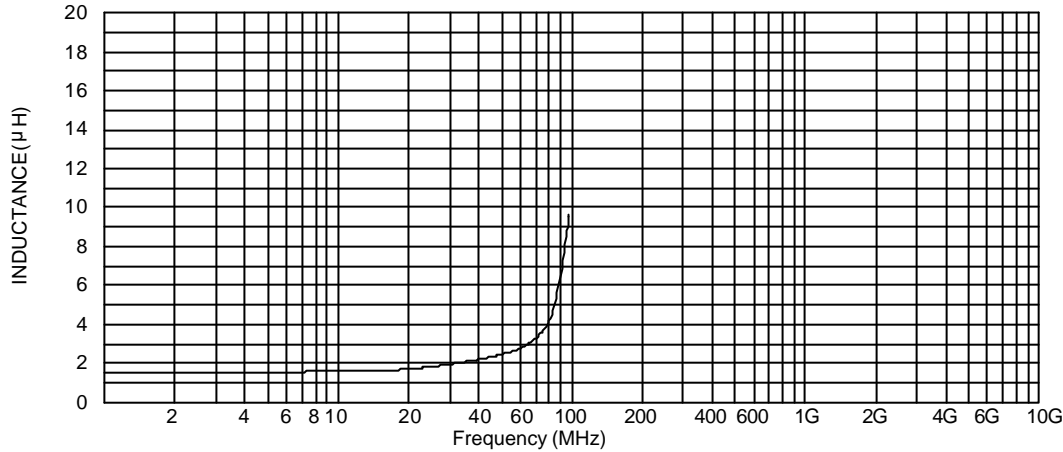


BCCL-2012E1-1R5K

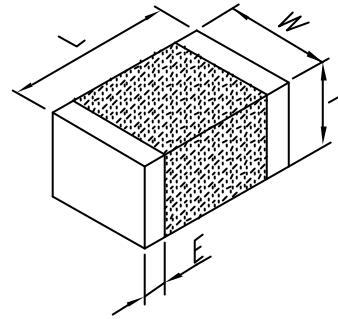
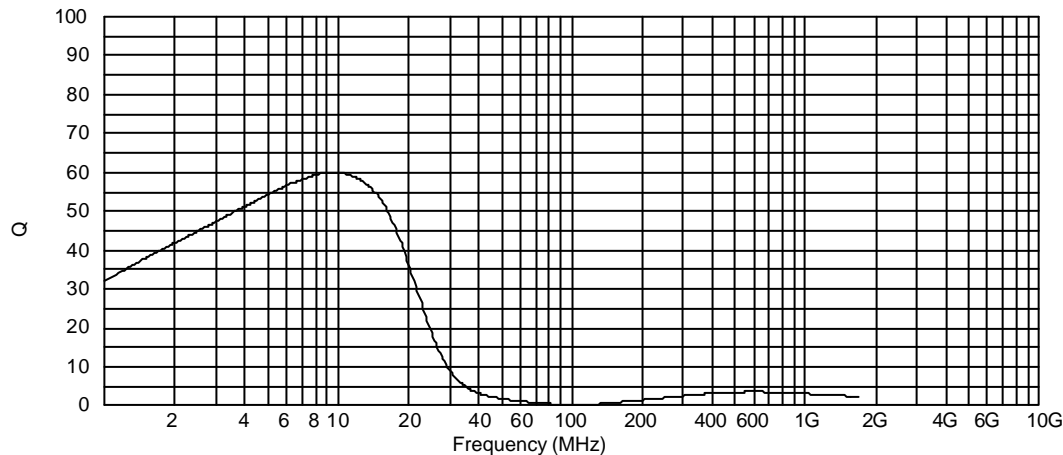
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.5	45	0.5	65	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

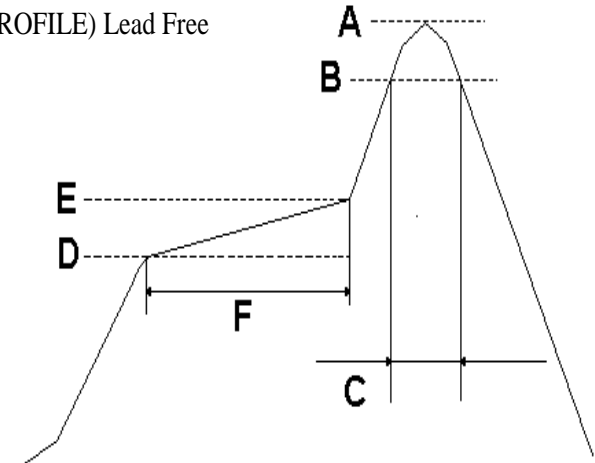
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30\pm10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

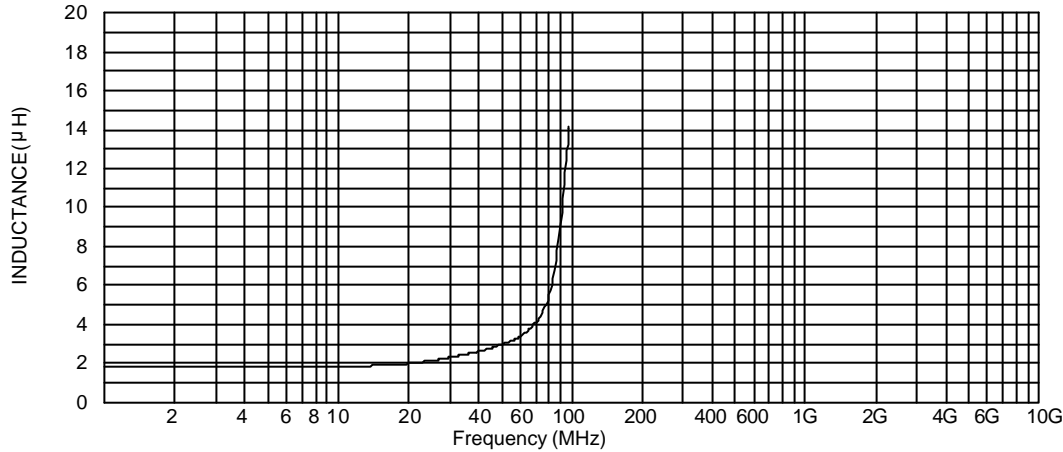


BCCL-2012E1-1R8K

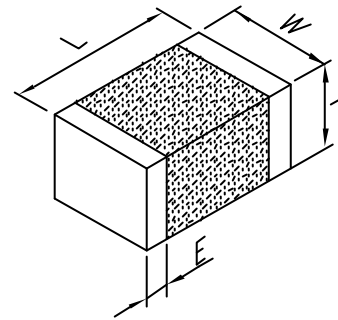
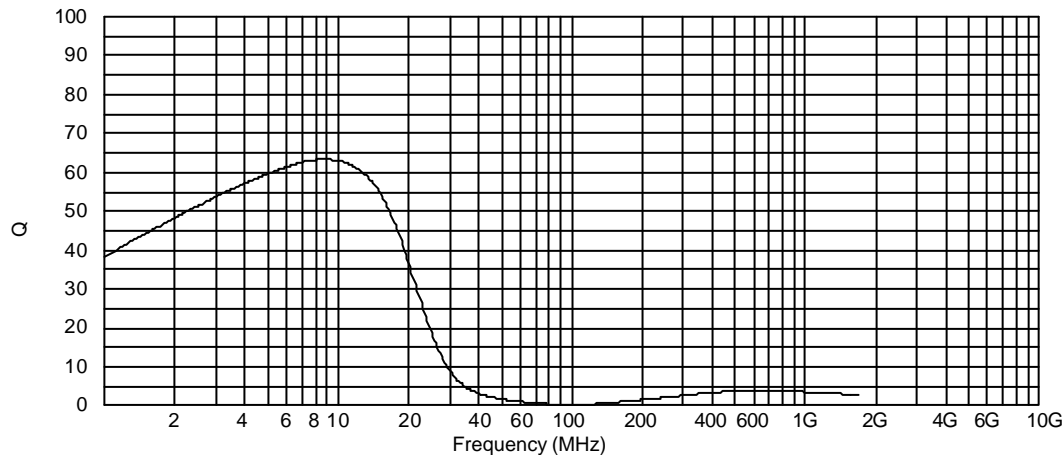
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
1.8	45	0.6	60	50

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

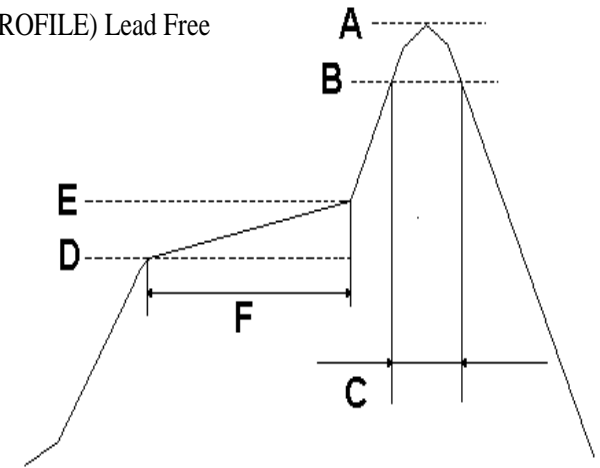
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

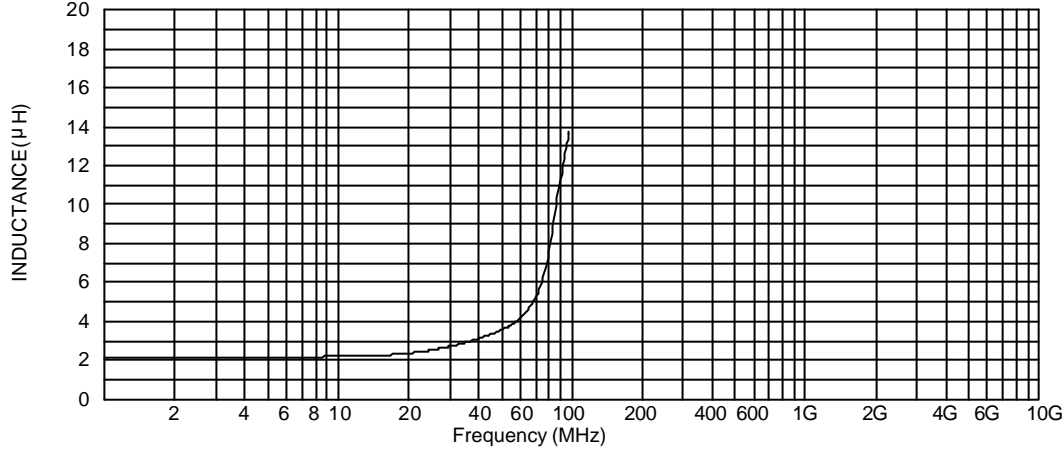


BCCL-2012E1-2R2K

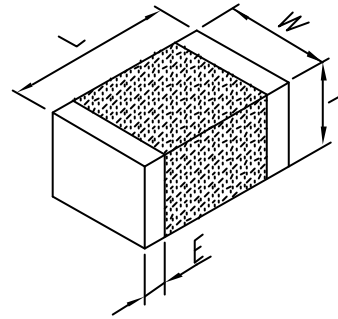
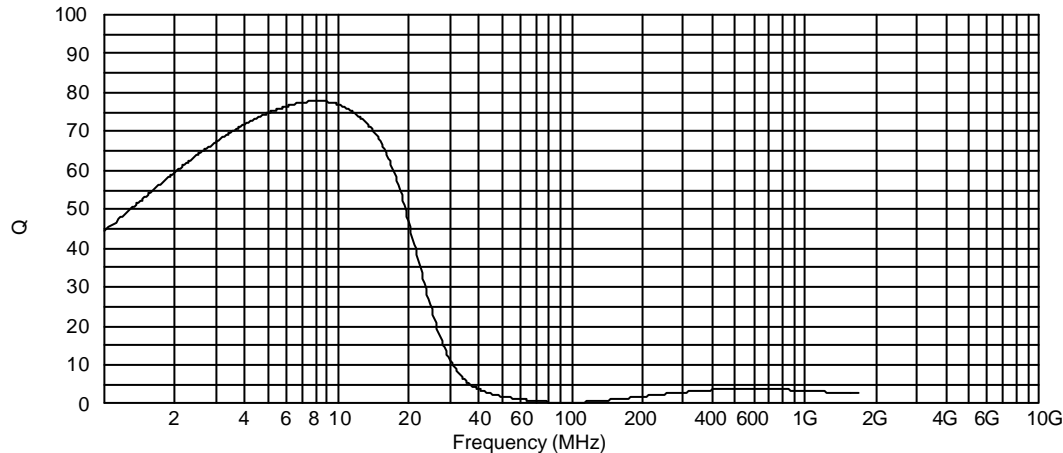
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
2.2	45	0.6	55	30

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 0.90(0.035) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

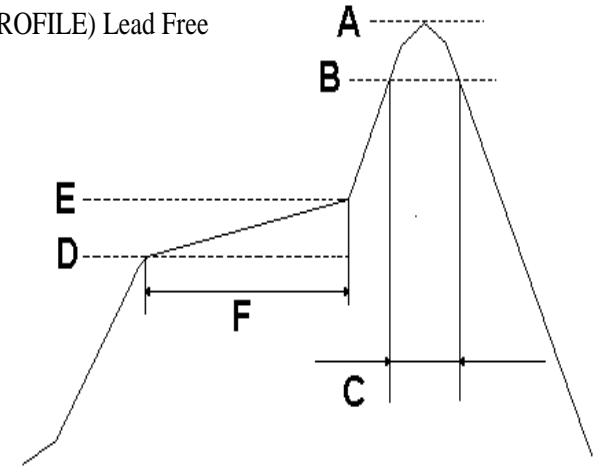
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec

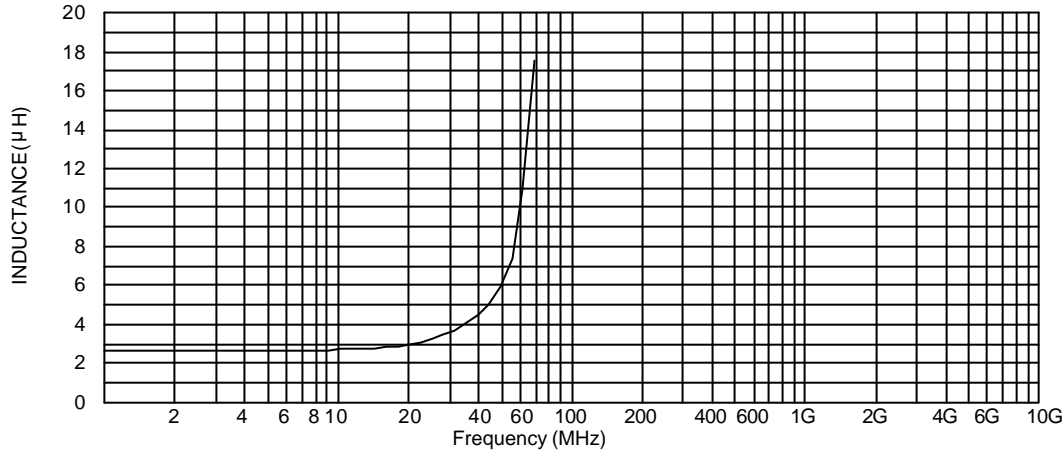


BCCL-2012E1-2R7K

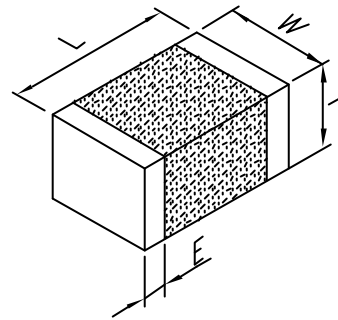
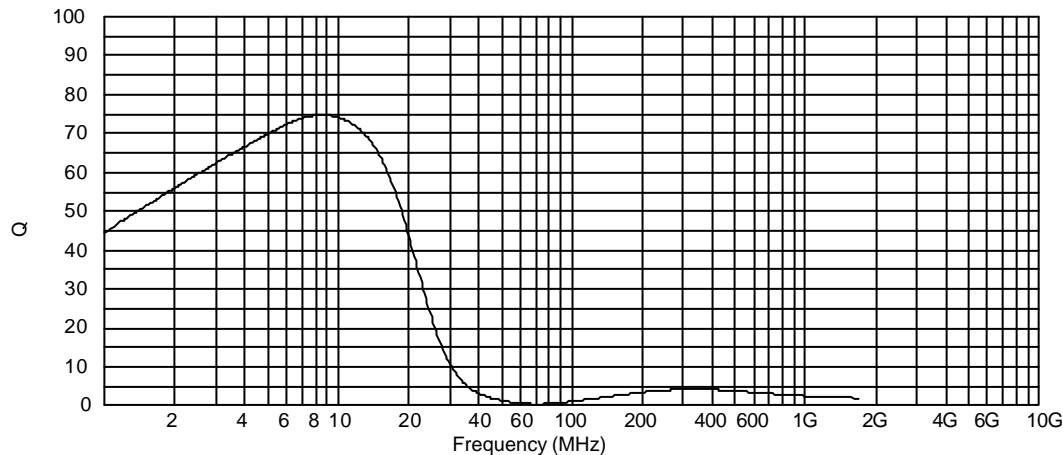
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
2.7	45	0.7	50	30

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

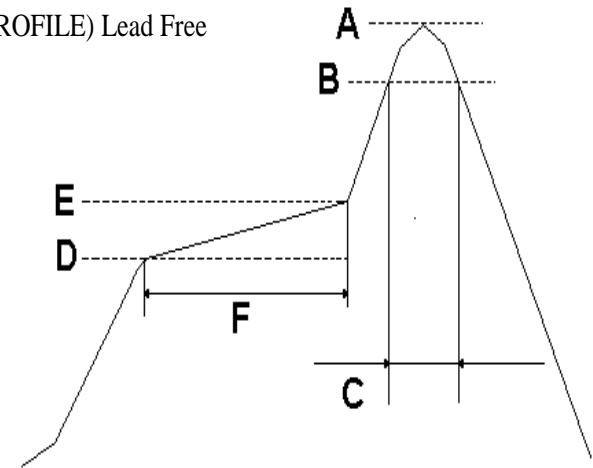
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec

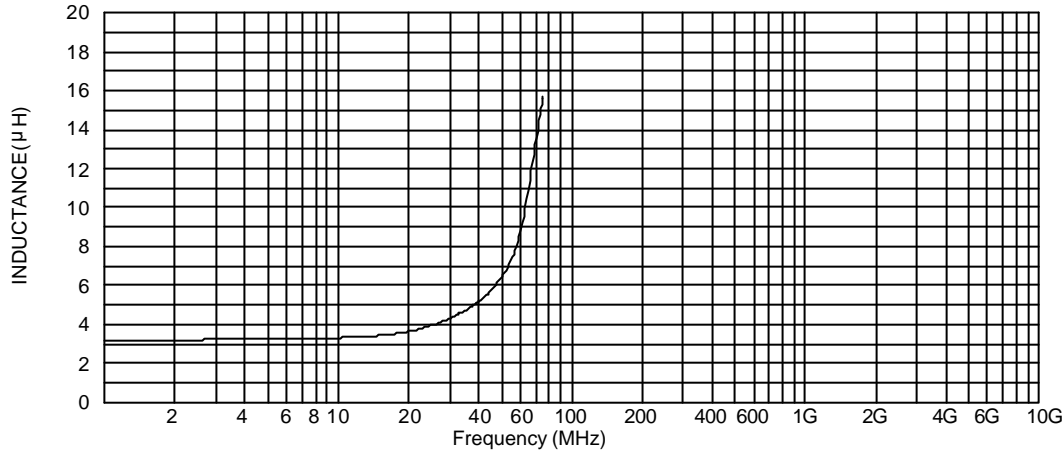


BCCL-2012E1-3R3K

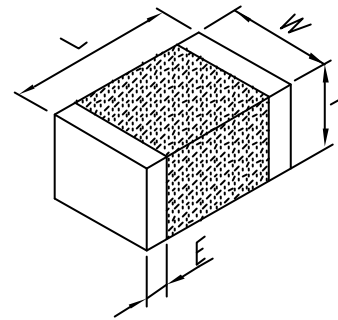
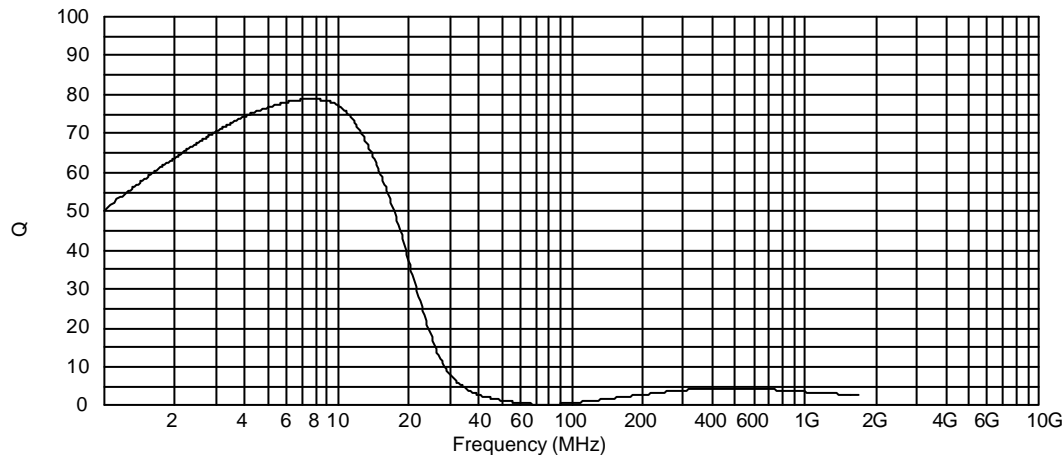
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
3.3	45	0.8	45	30

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

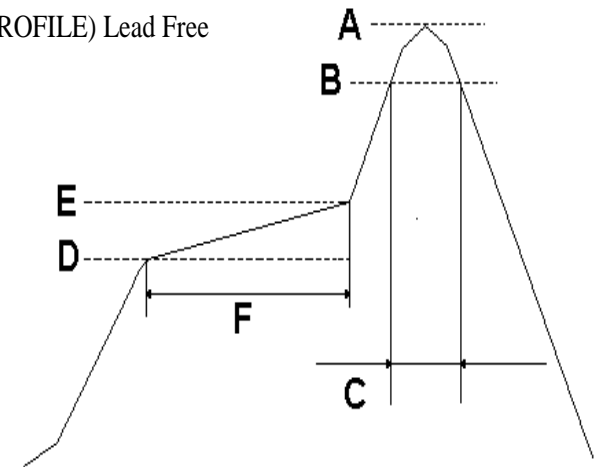
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

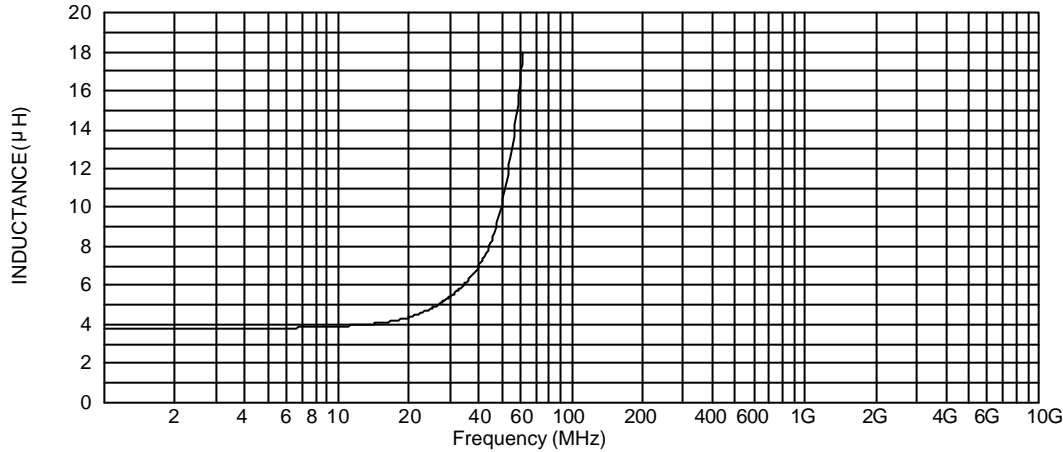


BCCL-2012E1-3R9K

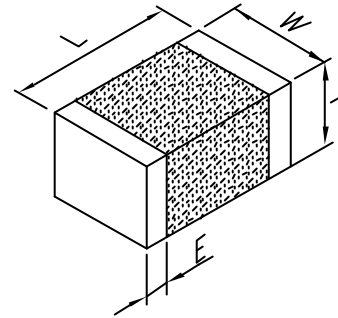
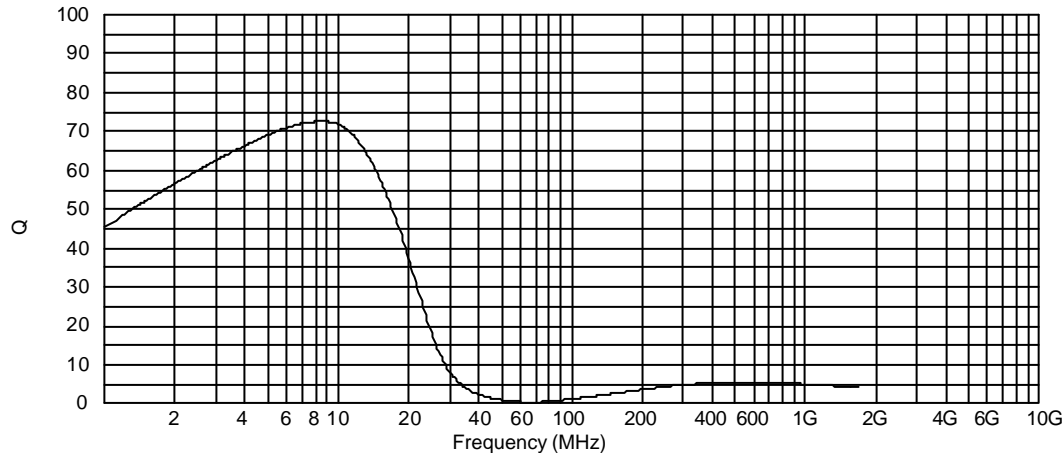
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
3.9	45	0.9	44	30

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

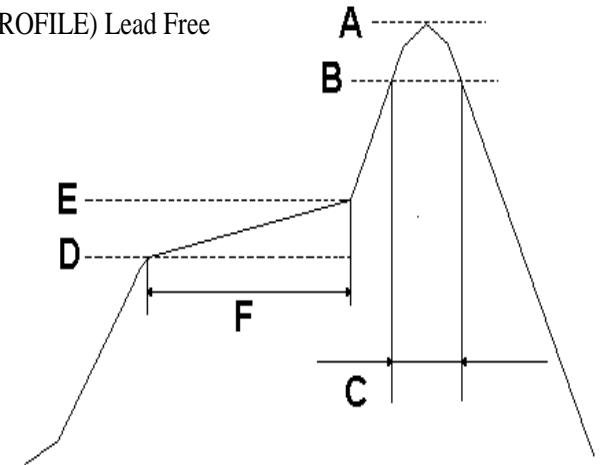
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

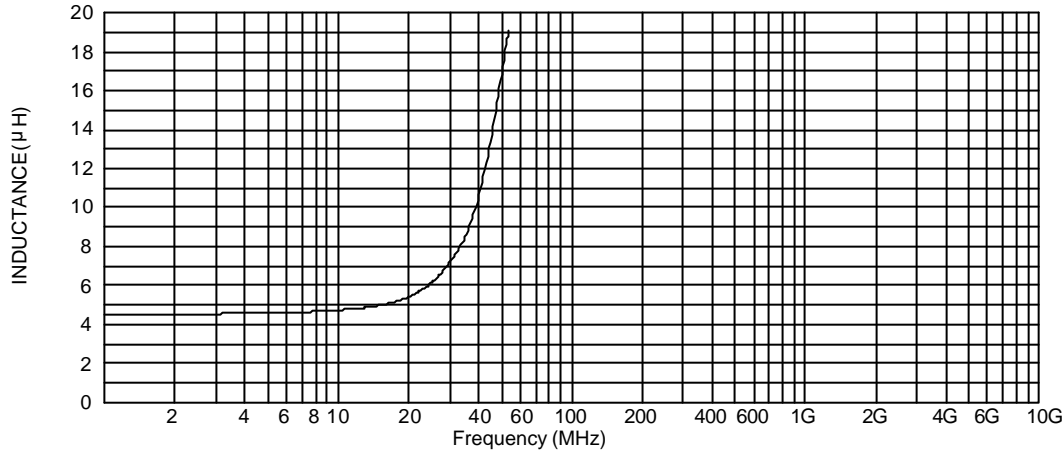


BCCL-2012E1-4R7K

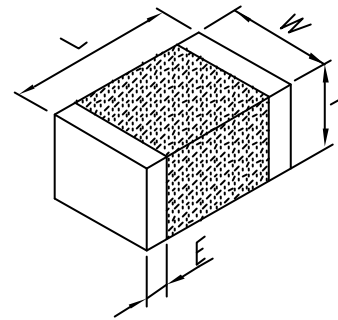
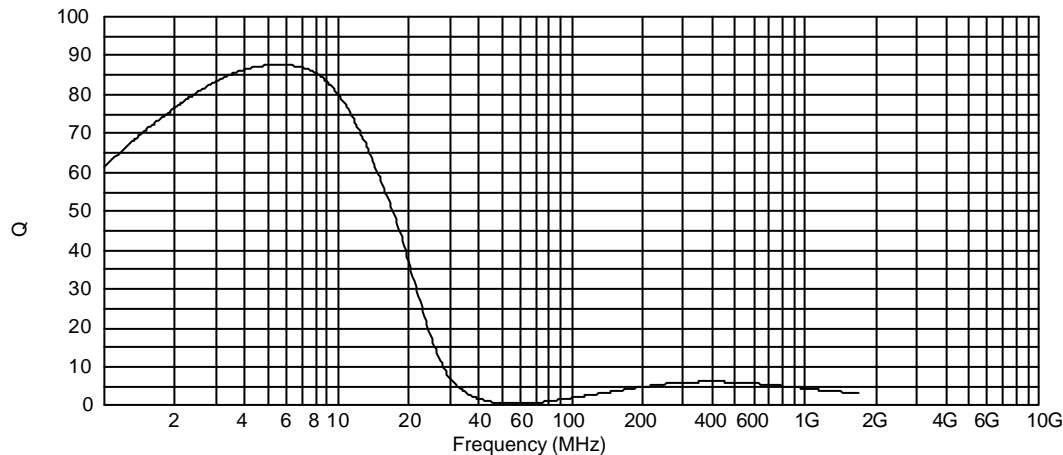
ELECTRICAL CHARACTERISTICS:

L@10MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
4.7	45	1.0	41	30

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

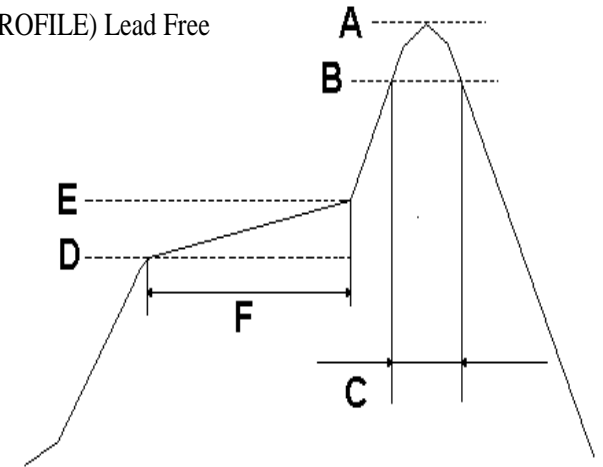
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

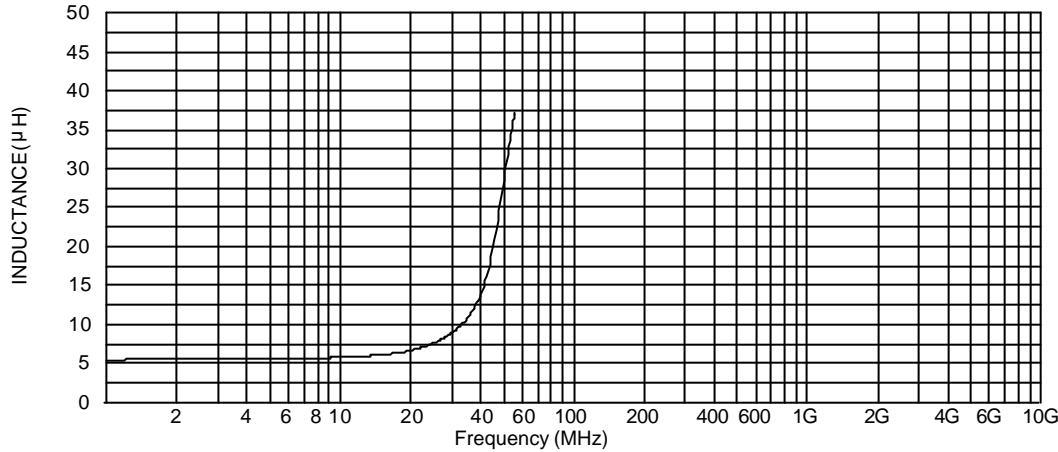


BCCL-2012E1-5R6K

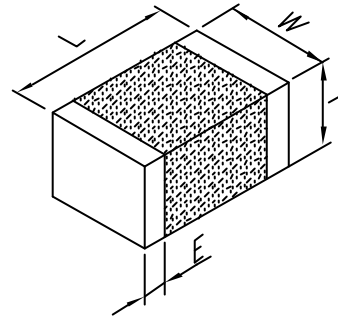
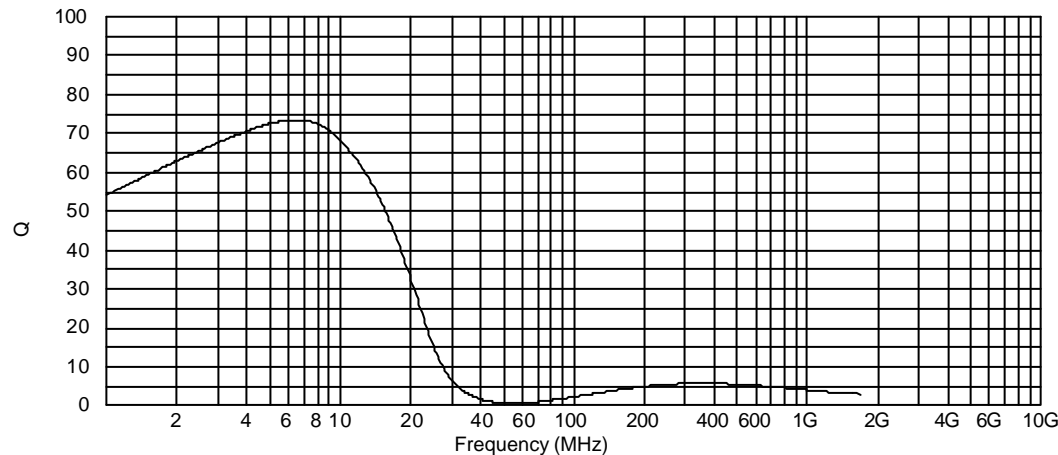
ELECTRICAL CHARACTERISTICS:

L@4MHz ($\mu H \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
5.6	50	0.90	37	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

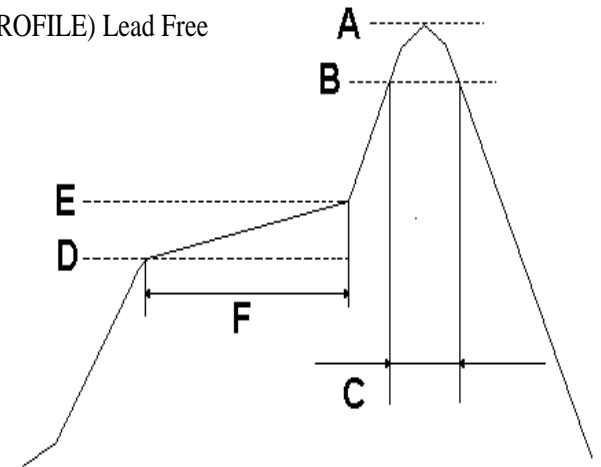
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec

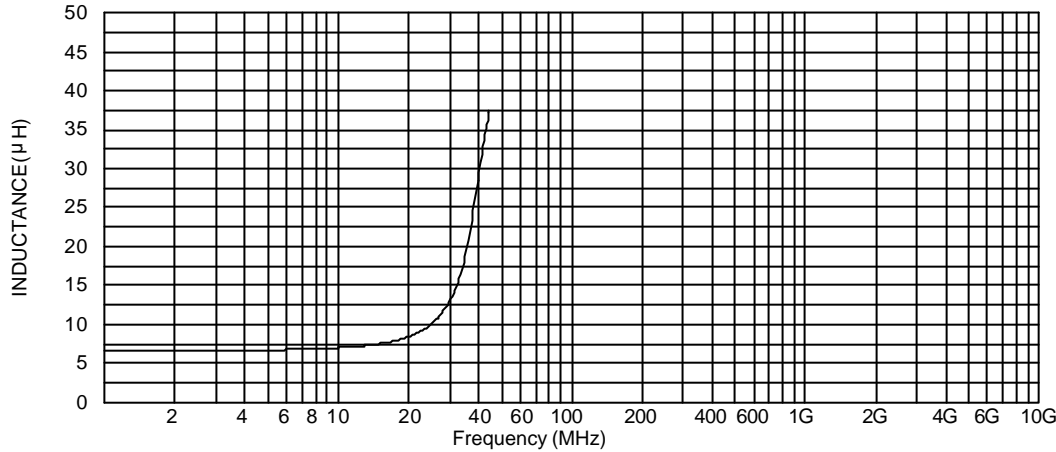


BCCL-2012E1-6R8K

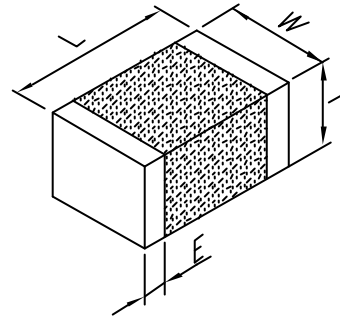
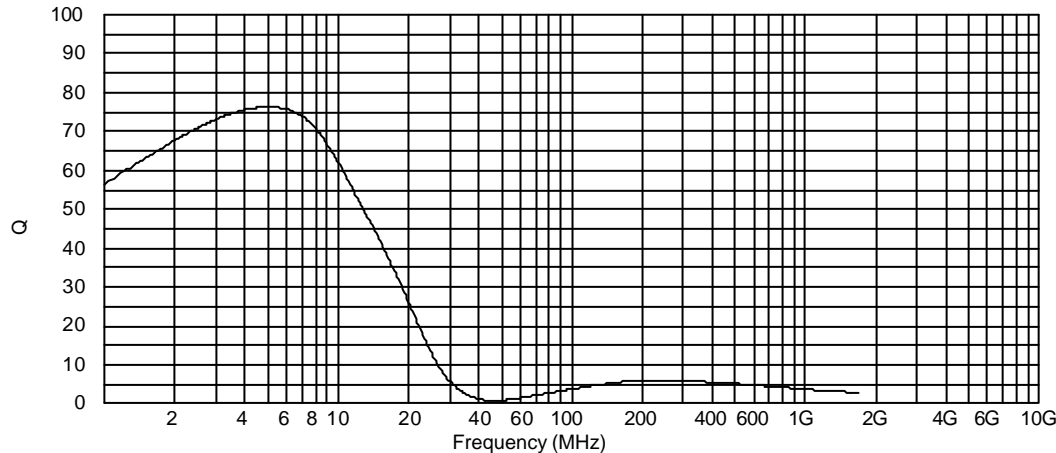
ELECTRICAL CHARACTERISTICS:

L@4MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
6.8	50	1.00	34	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) ± 0.200(0.008)
- W 1.25(0.049) ± 0.200(0.008)
- T 1.25(0.049) ± 0.200(0.008)
- E 0.50(0.020) ± 0.300(0.012)

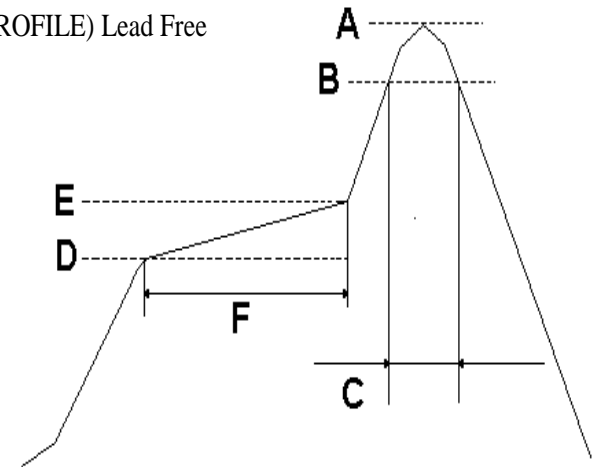
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	$30 \pm 10 \text{ sec}$
D	150
E	180
F	$90 \pm 30 \text{ sec}$

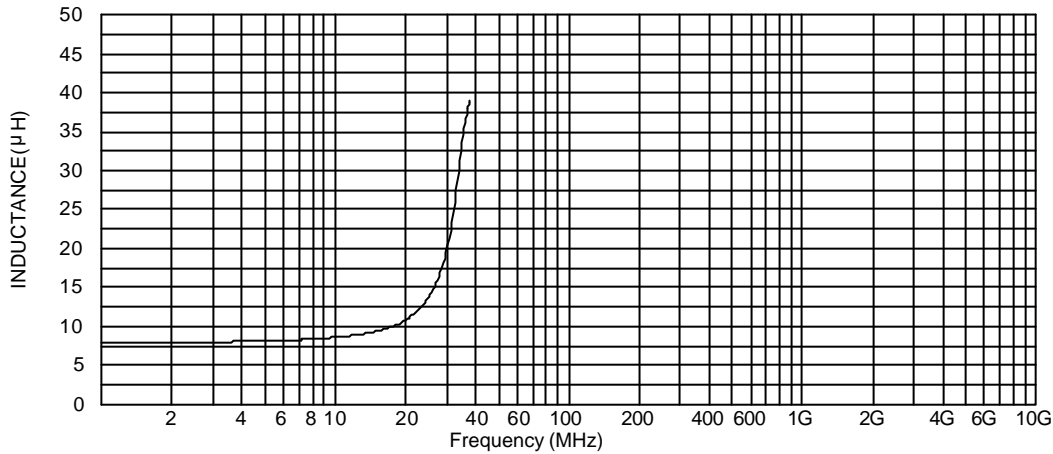


BCCL-2012E1-8R2K

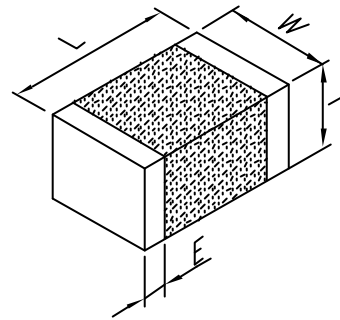
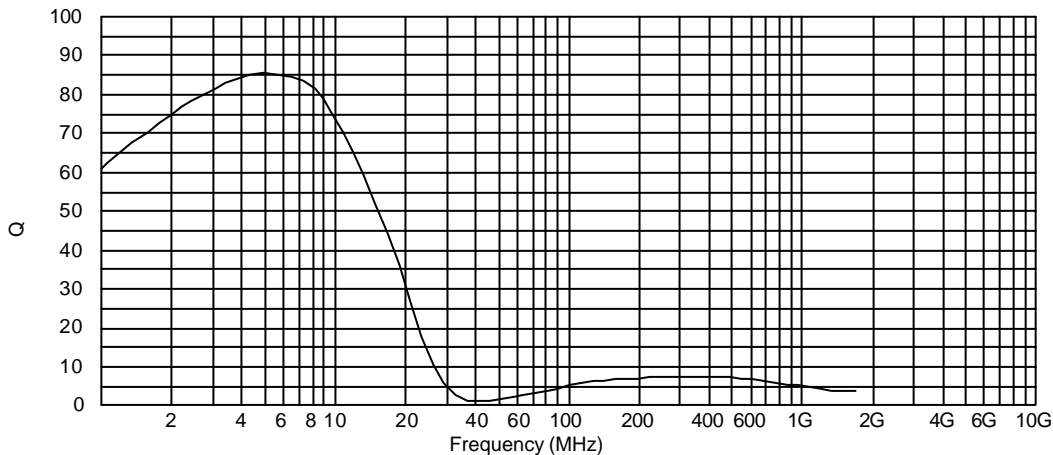
ELECTRICAL CHARACTERISTICS:

L@4MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
8.2	50	1.10	30	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) ± 0.200(0.008)
- W 1.25(0.049) ± 0.200(0.008)
- T 1.25(0.049) ± 0.200(0.008)
- E 0.50(0.020) ± 0.300(0.012)

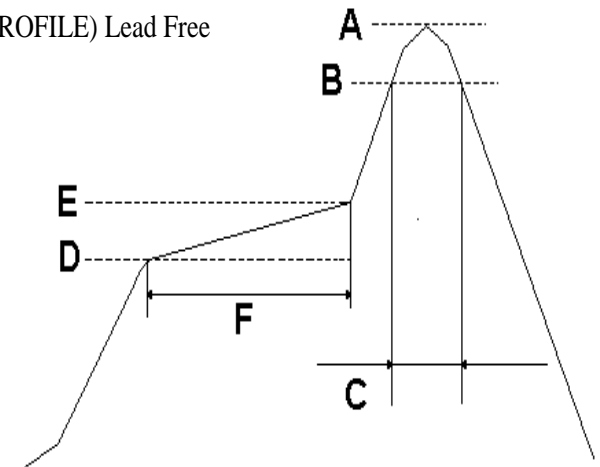
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	$30 \pm 10 \text{ sec}$
D	150
E	180
F	$90 \pm 30 \text{ sec}$

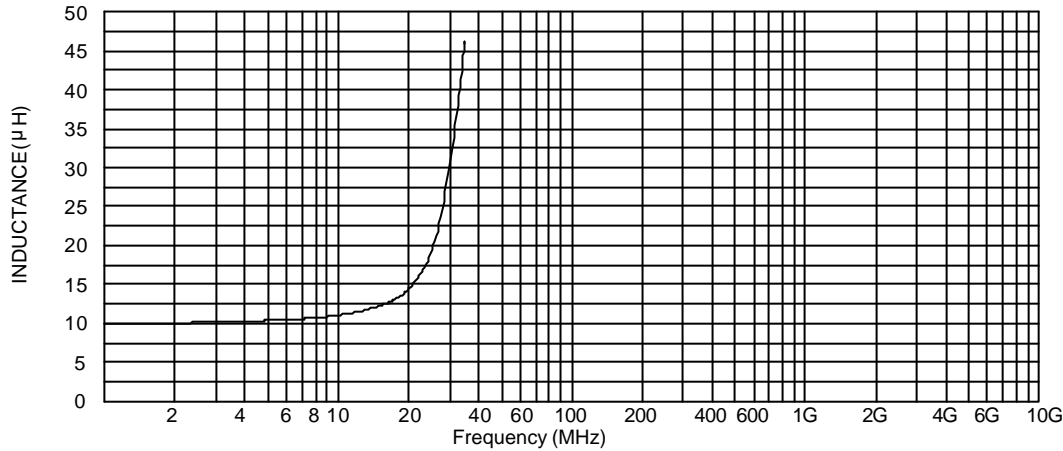


BCCL-2012E1-10RK

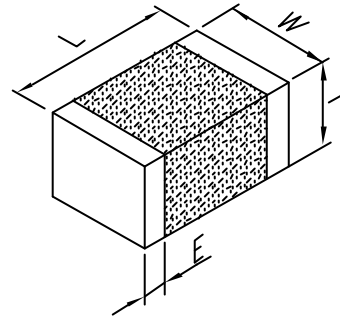
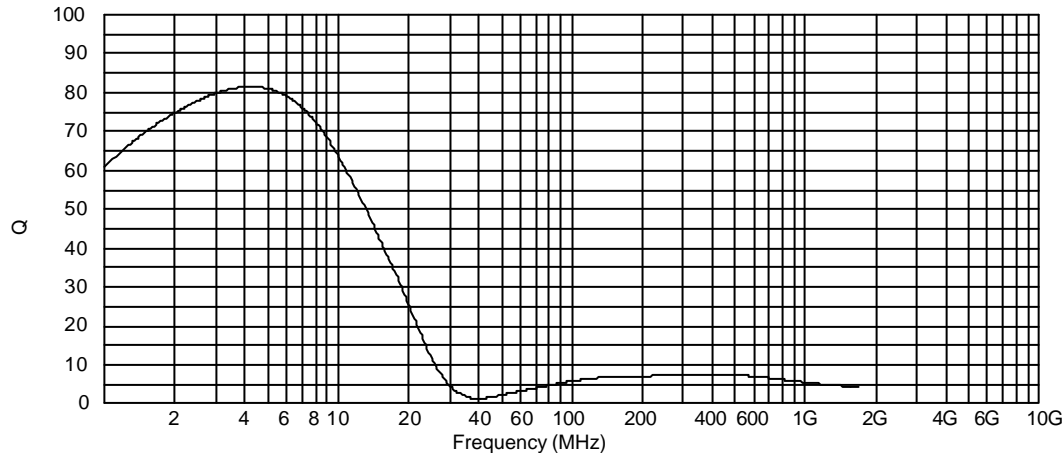
ELECTRICAL CHARACTERISTICS:

L@2MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
10	50	1.00	28	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

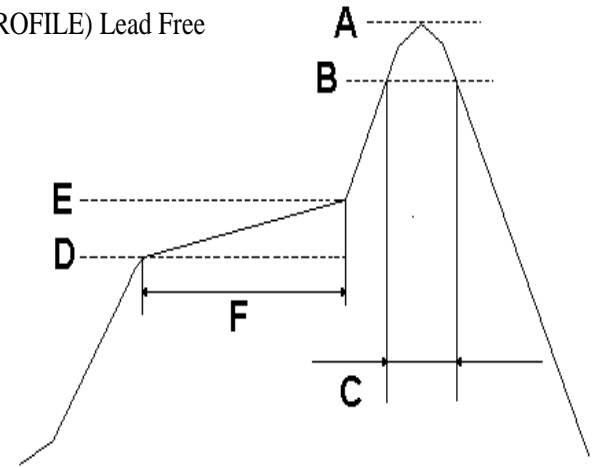
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

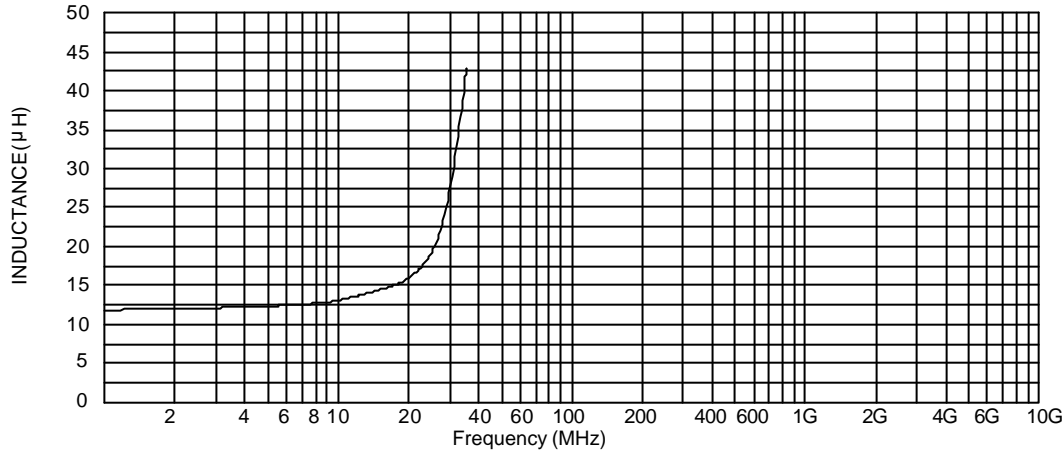


BCCL-2012E1-12RK

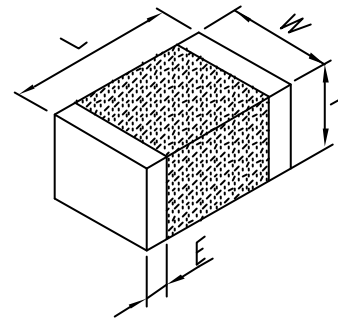
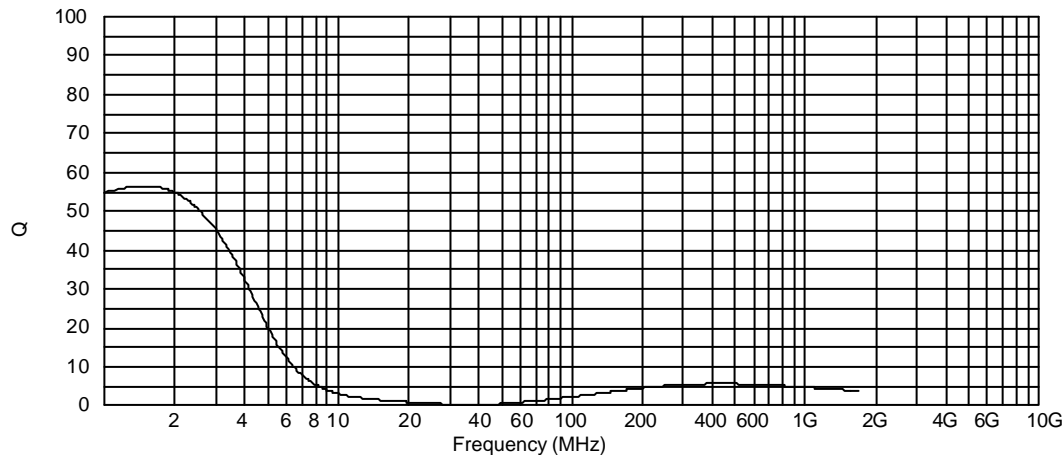
ELECTRICAL CHARACTERISTICS:

L@2MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
12	50	1.10	26	15

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

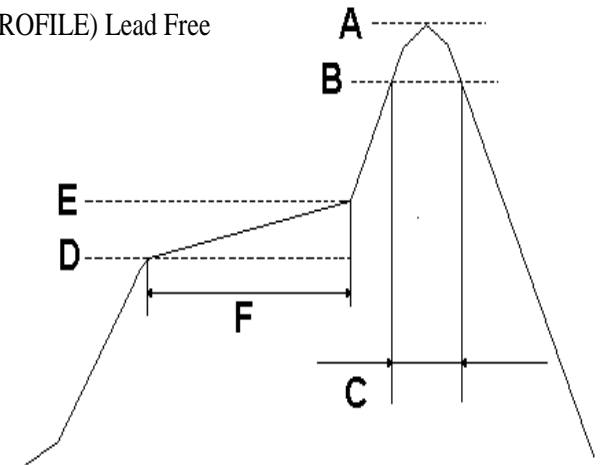
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

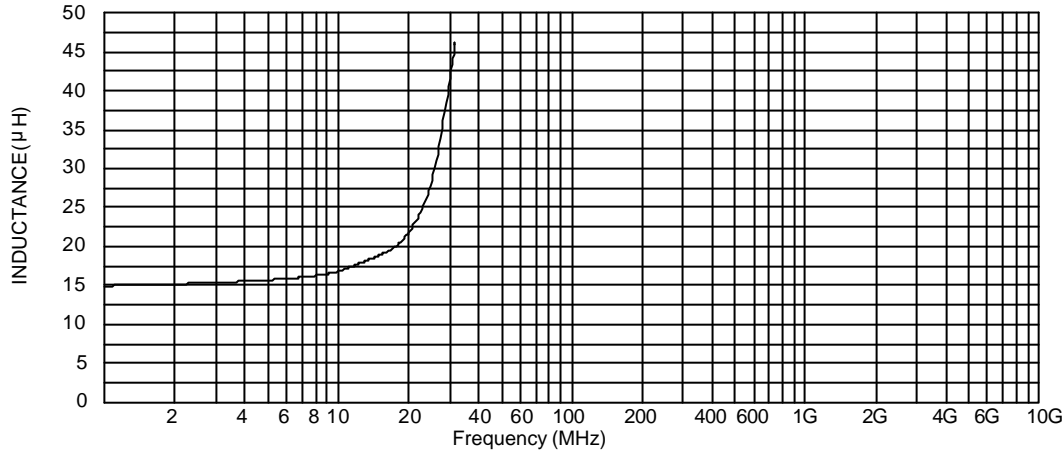


BCCL-2012E1-15RK

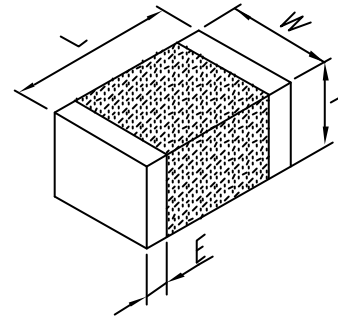
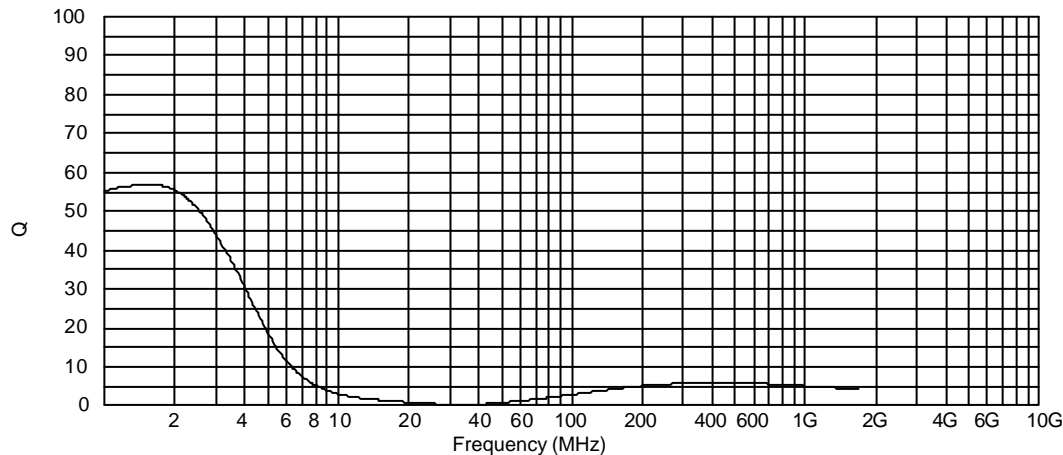
ELECTRICAL CHARACTERISTICS:

L@1MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
15	35	0.8	22	5

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

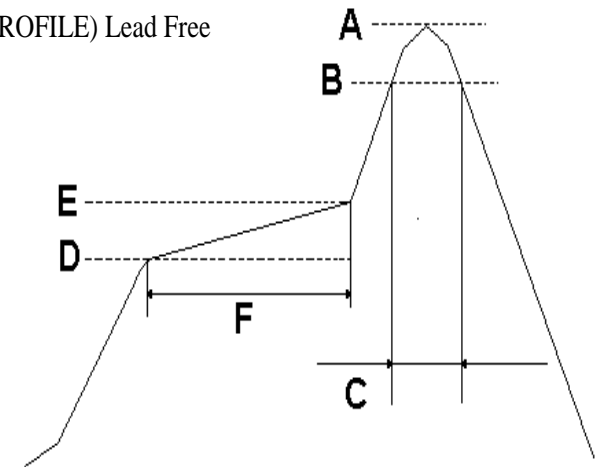
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 \pm 5/-0
B	230
C	30 \pm 10 sec
D	150
E	180
F	90 \pm 30sec

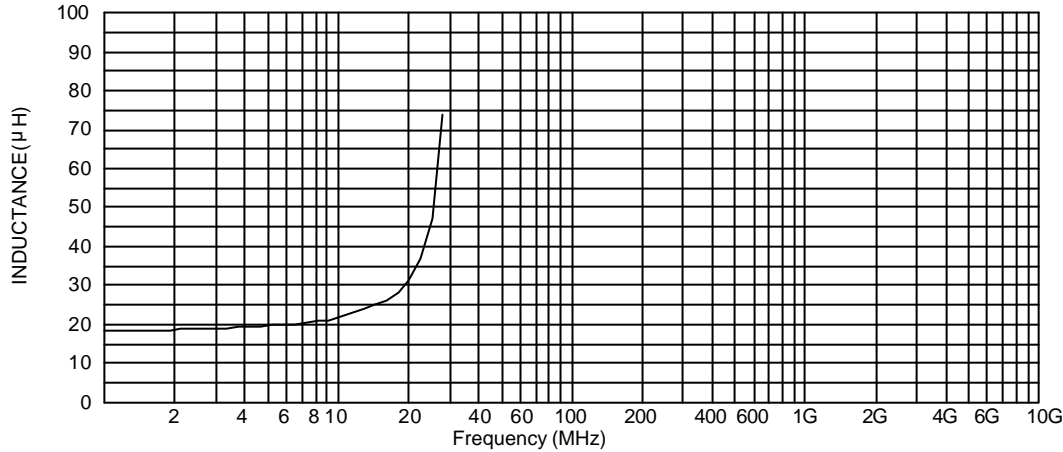


BCCL-2012E1-18RK

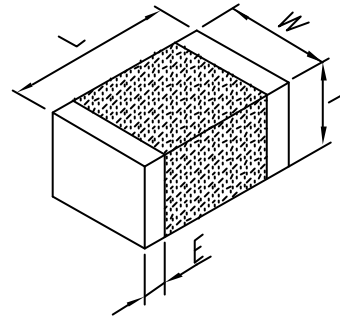
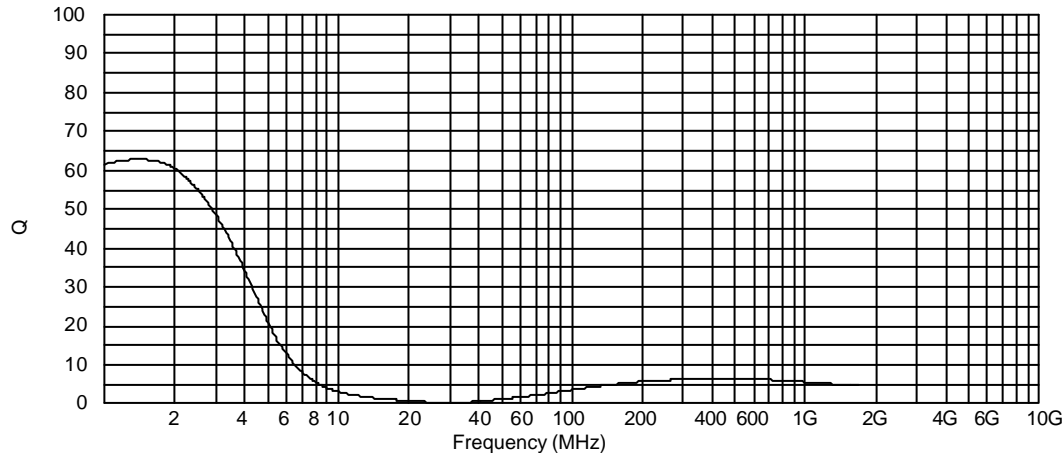
ELECTRICAL CHARACTERISTICS:

L@1MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
18	35	0.90	21	5

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

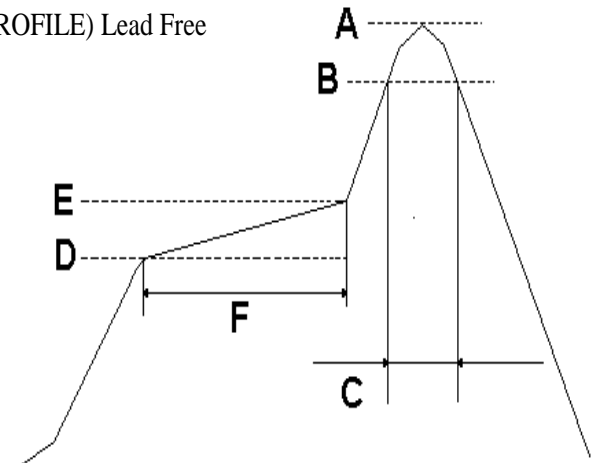
NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	$260 \pm 5/-0$
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30 sec

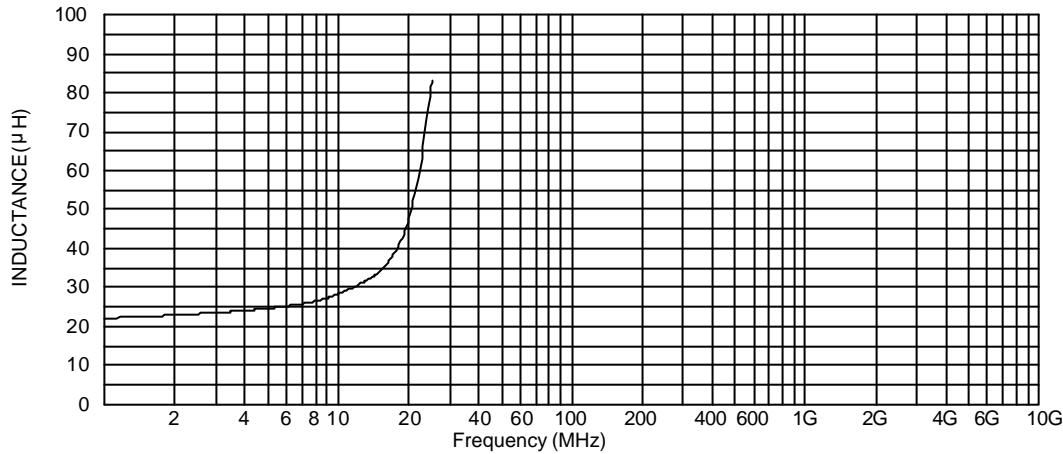


BCCL-2012E1-22RK

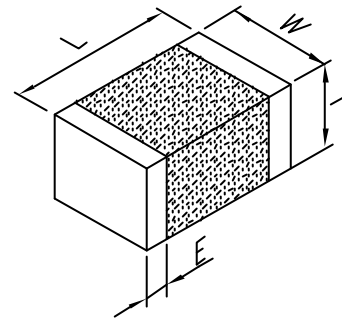
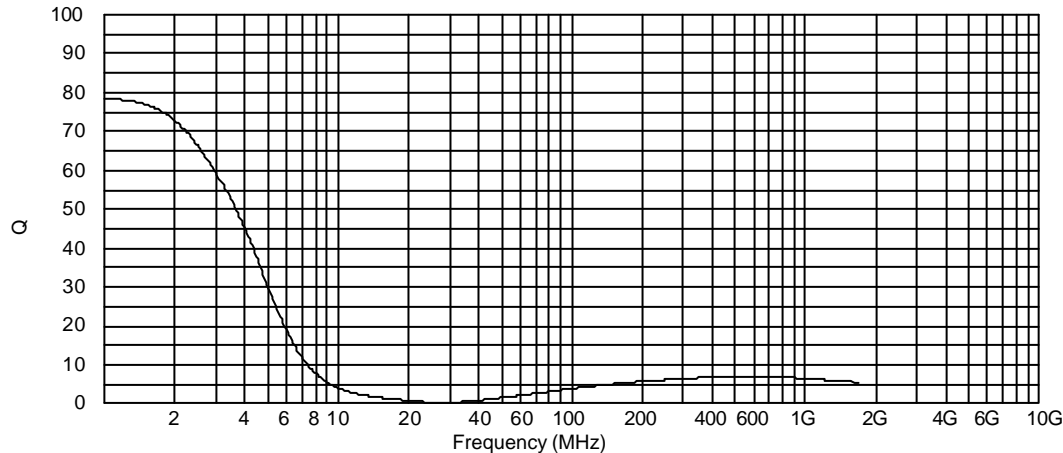
ELECTRICAL CHARACTERISTICS:

L@1MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
22	35	1.10	19	5

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

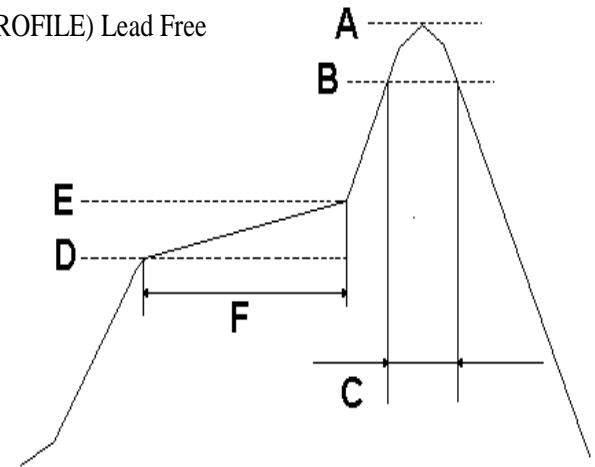
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 \pm 5/-0
B	230
C	30 \pm 10 sec
D	150
E	180
F	90 \pm 30sec

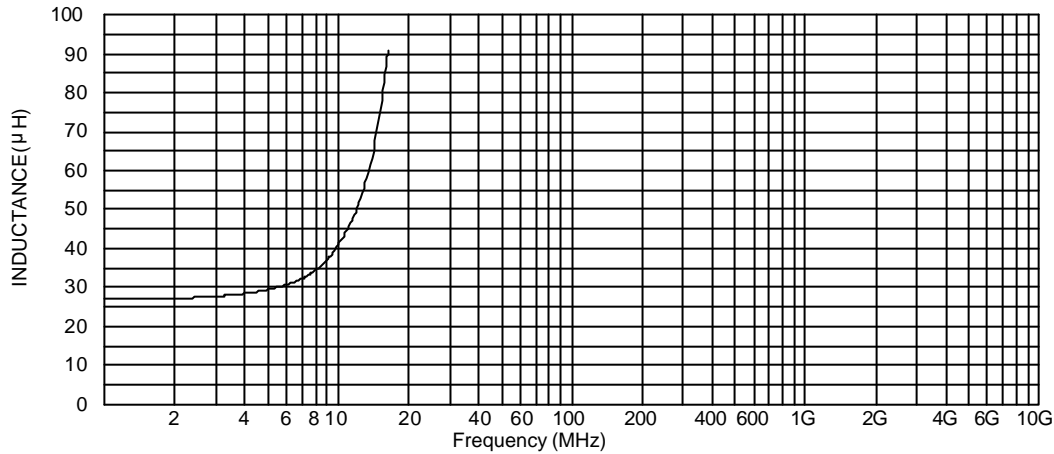


BCCL-2012E1-27RK

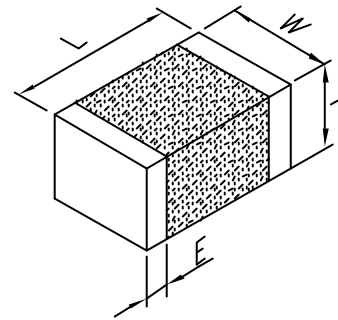
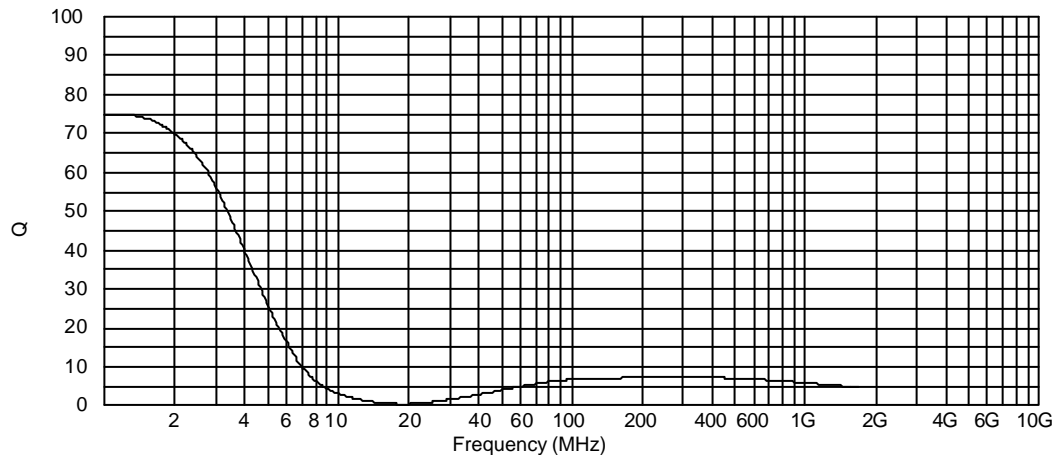
ELECTRICAL CHARACTERISTICS:

L@1MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
27	30	1.15	14	5

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) ± 0.200(0.008)
- W 1.25(0.049) ± 0.200(0.008)
- T 1.25(0.049) ± 0.200(0.008)
- E 0.50(0.020) ± 0.300(0.012)

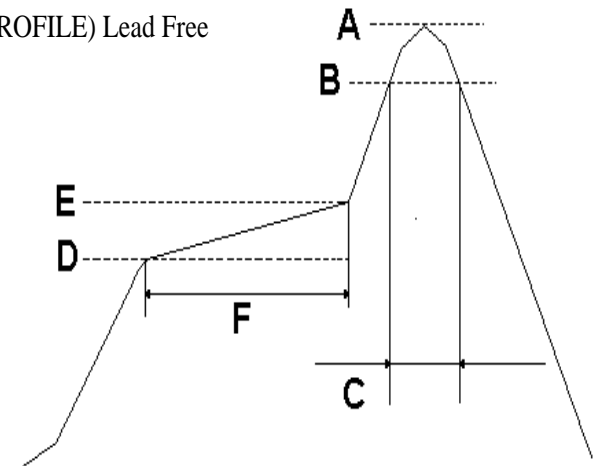
NOTES: UNLESS OTHERWISE SPECIFIED

- All edges and corners must be rounded.
- Dimensions are in millimeters (inches)
- Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	260 ± 5/-0
B	230
C	30 ± 10 sec
D	150
E	180
F	90 ± 30sec

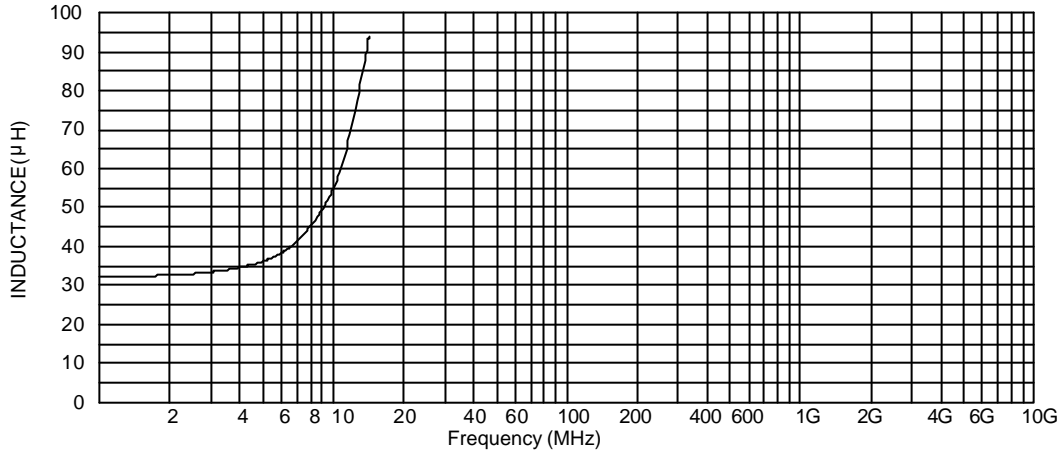


BCCL-2012E1-33RK

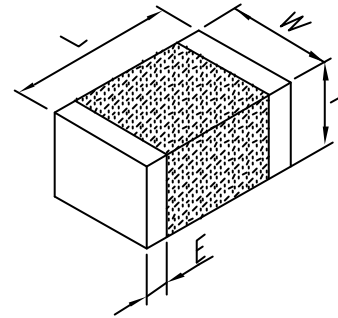
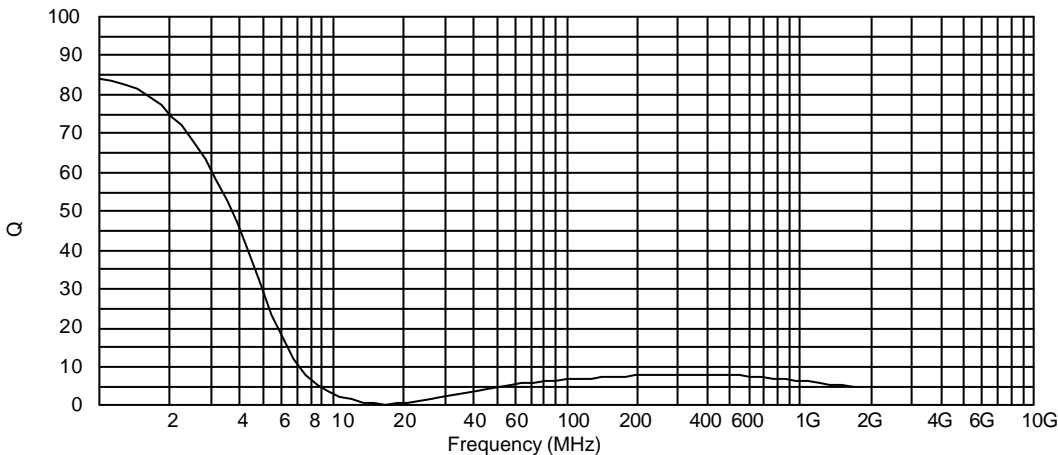
ELECTRICAL CHARACTERISTICS:

L@0.4MHz ($\mu\text{H} \pm 10\%$)	Q (min.)	DCR (max.)	S.R.F (MHz) (min.)	Rated Current (mA)
33	30	1.25	13	5

INDUCTANCE vs. FREQUENCY



Q vs. FREQUENCY CHARACTERISTICS



PHYSICAL DIMENSIONS:

- L 2.00(0.079) \pm 0.200(0.008)
- W 1.25(0.049) \pm 0.200(0.008)
- T 1.25(0.049) \pm 0.200(0.008)
- E 0.50(0.020) \pm 0.300(0.012)

NOTES: UNLESS OTHERWISE SPECIFIED

- 1.-All edges and corners must be rounded.
- 2.-Dimensions are in millimeters (inches)
- 3.-Taped and Reeled per current EIA specification.

Recommended Soldering Conditions

(REFLOW TEMPERATURE PROFILE) Lead Free

A	<i>260 \pm 5/-0</i>
B	<i>230</i>
C	<i>30 \pm 10 sec</i>
D	<i>150</i>
E	<i>180</i>
F	<i>90 \pm 30sec</i>

